



Dreams of Automation Technologies

COMIZOA

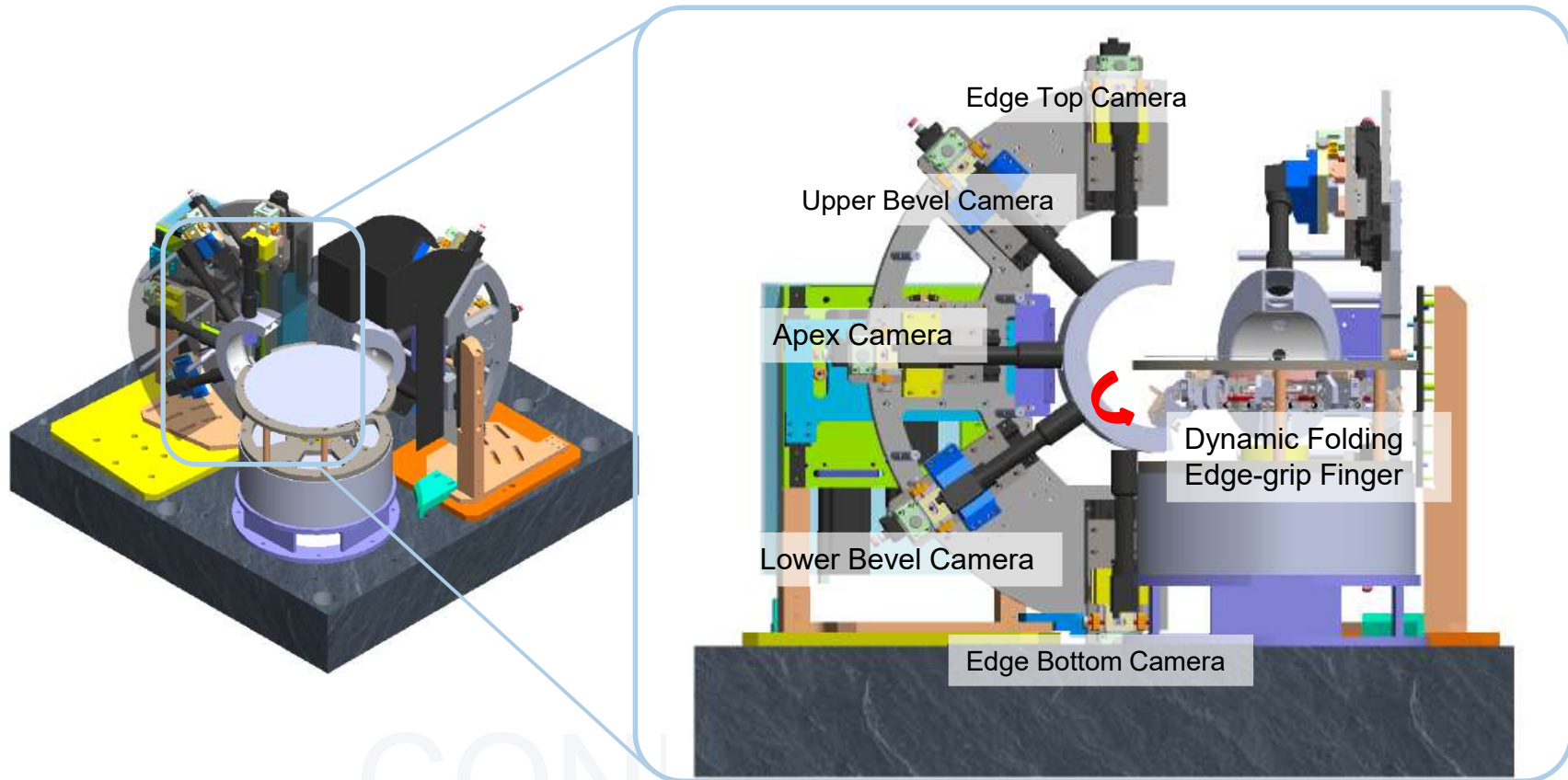
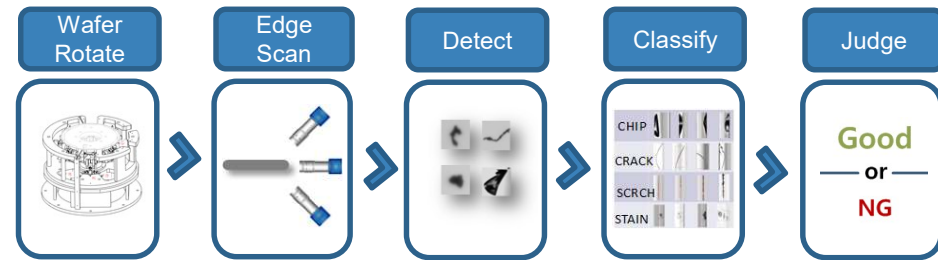
CONFIDENTIAL

Dreams of Automation Technologies

Technologies


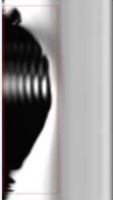



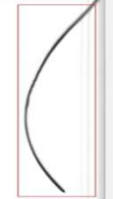






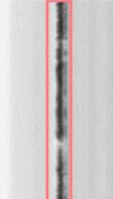

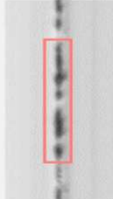





Machine Vision and Mechanics

Edge Inspection

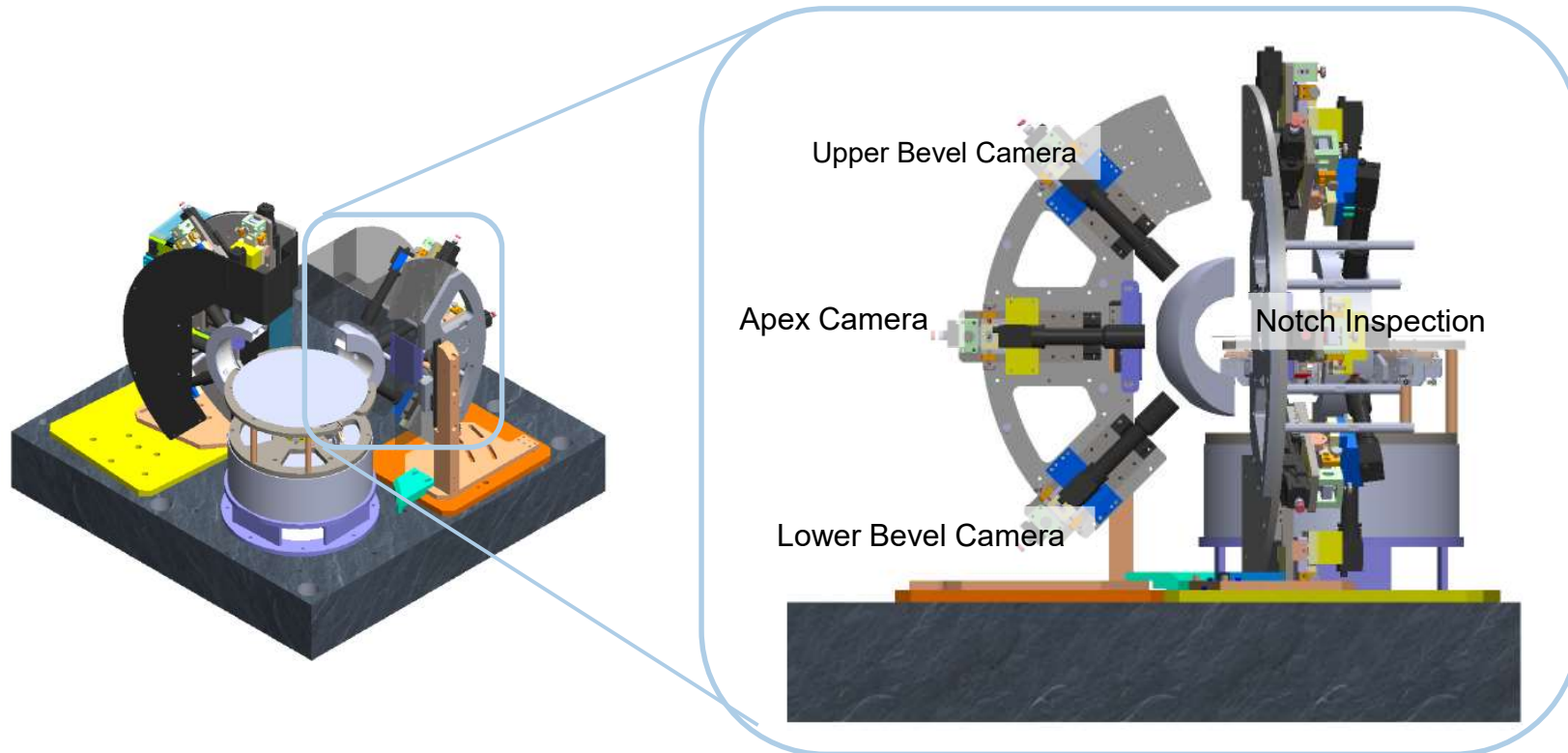
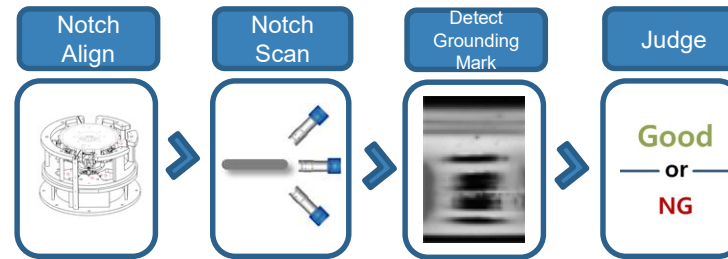


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Edge Defect

Defect Type	Defect Image Samples				
Chip					
Crack					
Sparkle					
Stain					

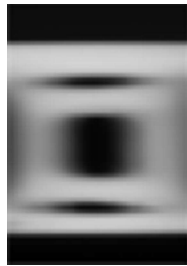
Notch Inspection



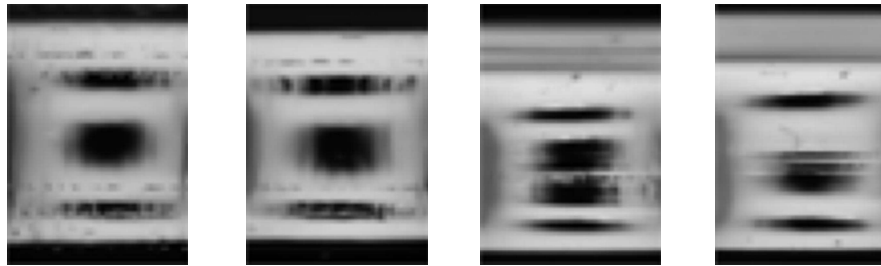
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Notch Defect

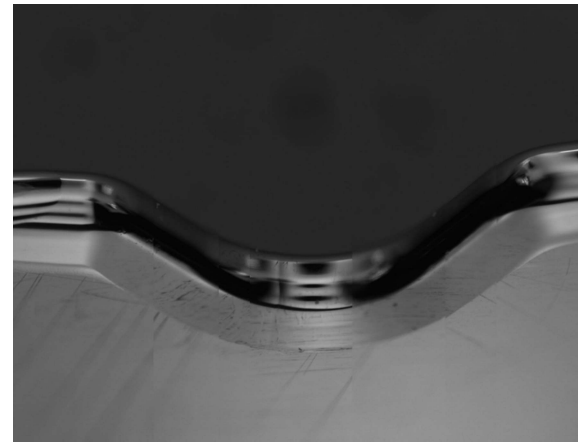
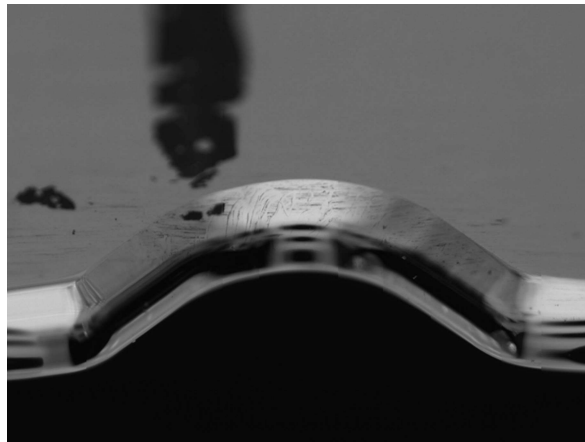
OK



NG (Wheel mark detected)



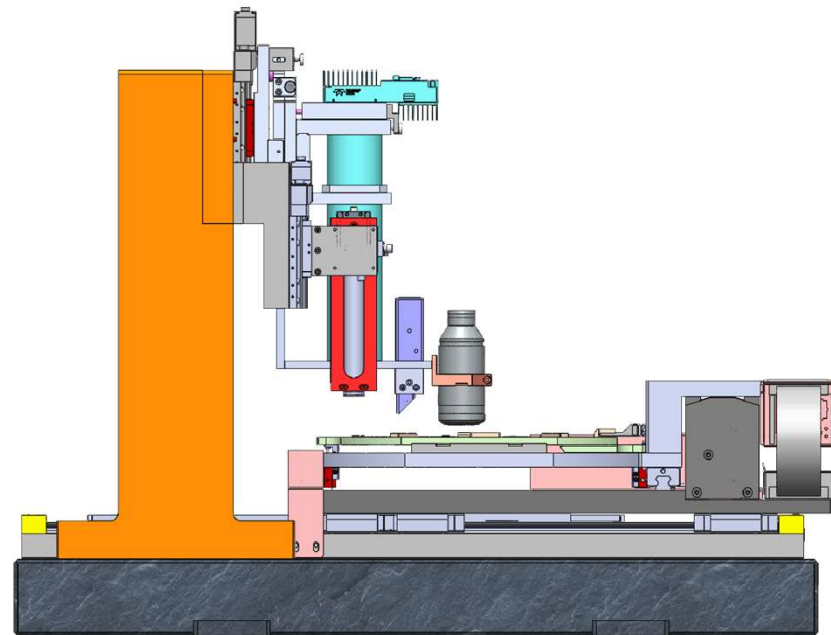
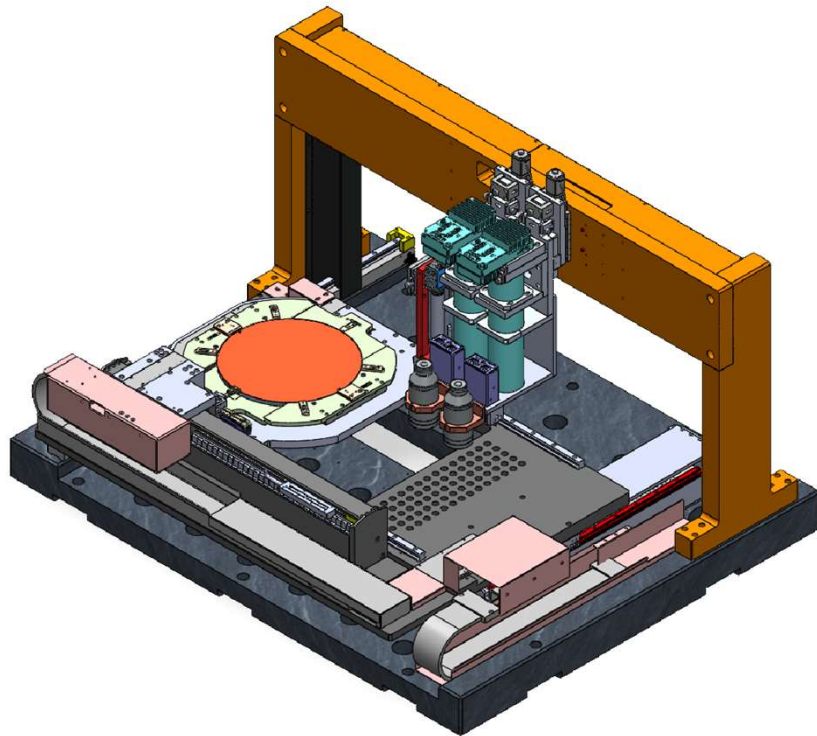
Notch Apex Images



Upper Bevel Image

Lower Bevel Image

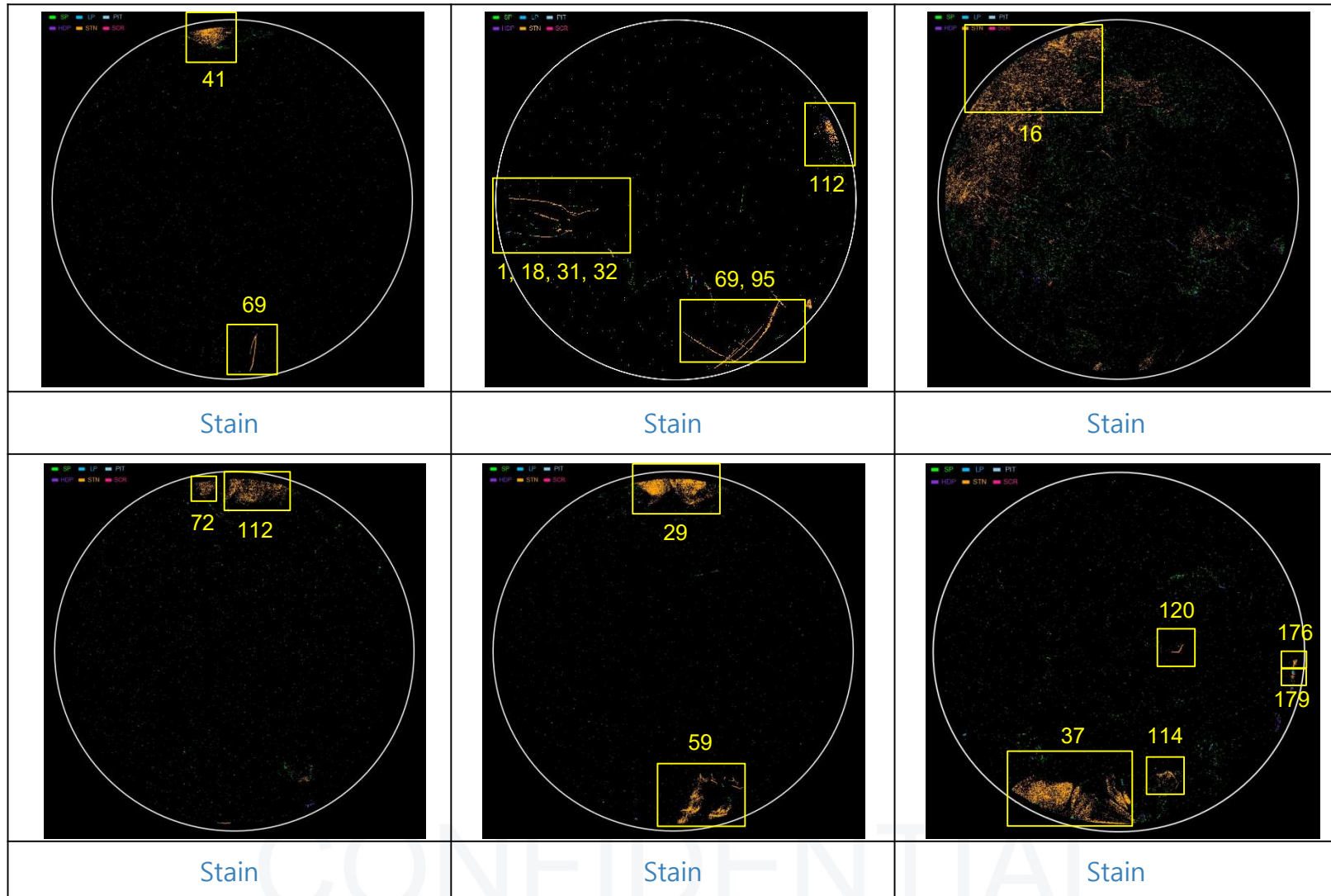
Surface Inspection



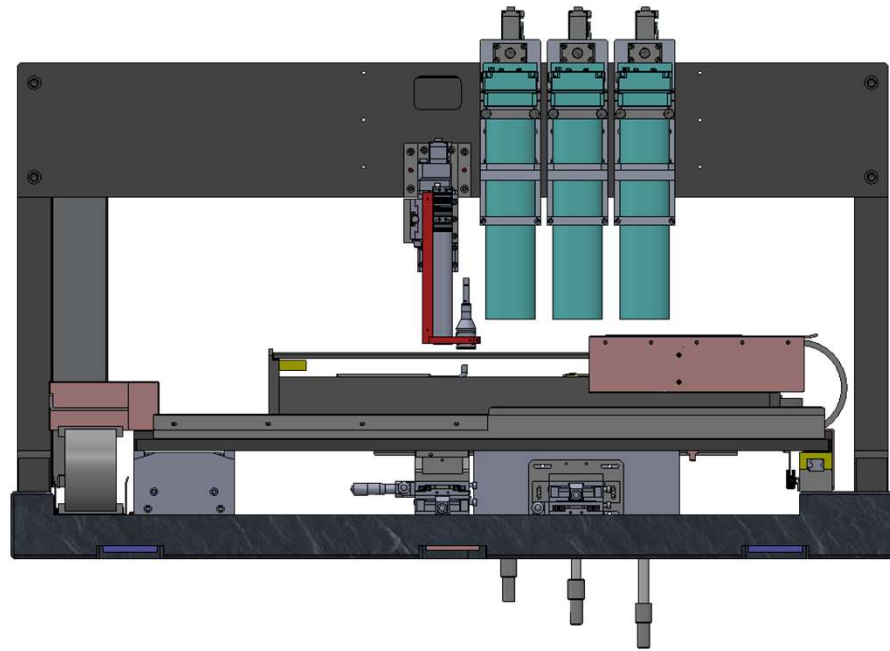
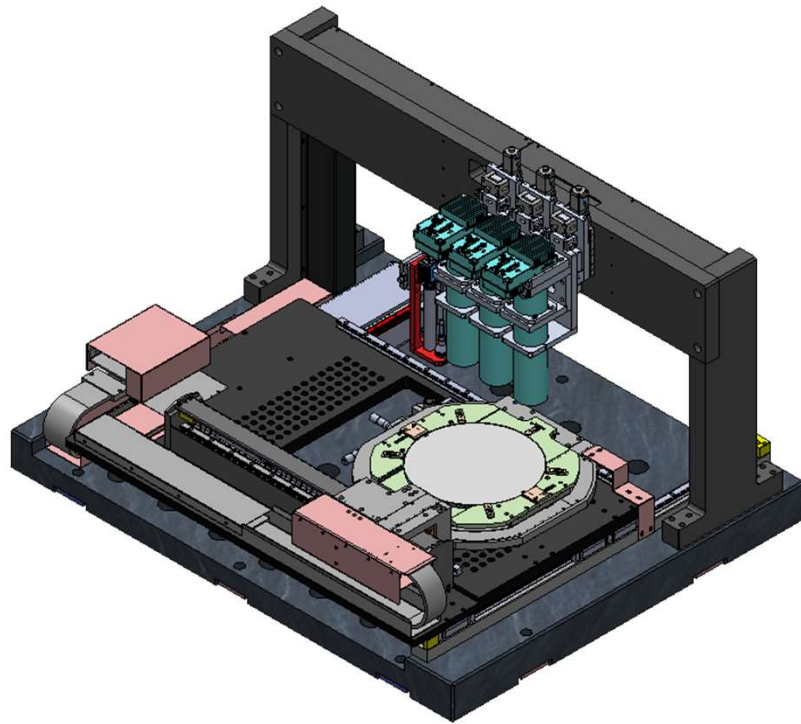
※ Front side & Backside inspection is performed at the same time.

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Surface Defect

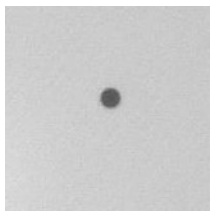
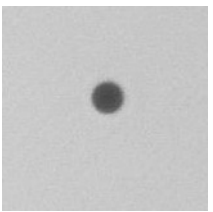
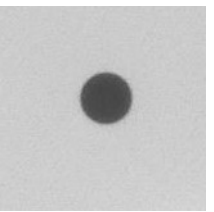
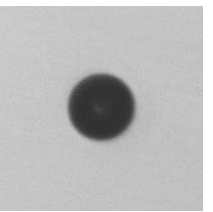
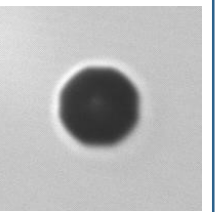
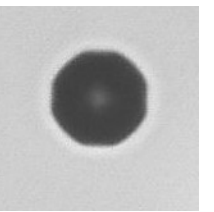


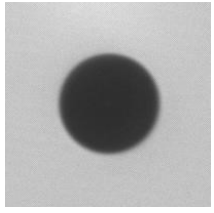
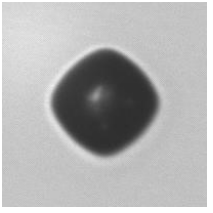
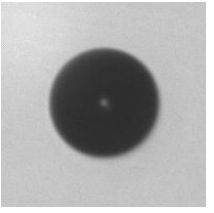
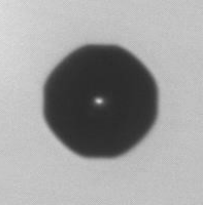
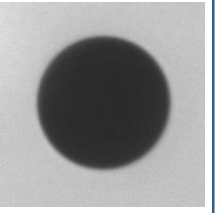
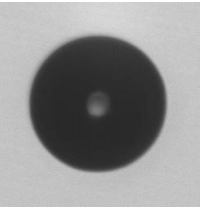
Air-pocket Inspection



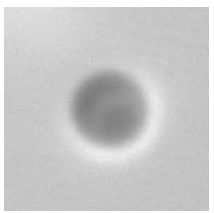
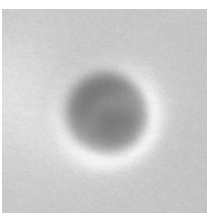
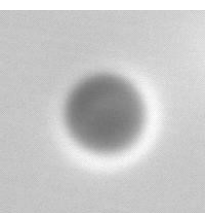
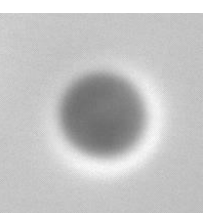
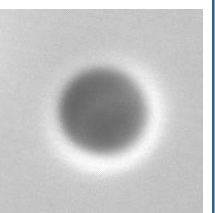
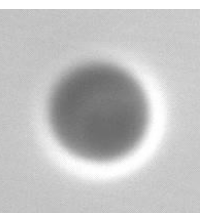
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Air-pocket Defect

Size	21.6 μm	35.4 μm	55.3 μm	92.8 μm	112.2 μm	135.8 μm
Image						

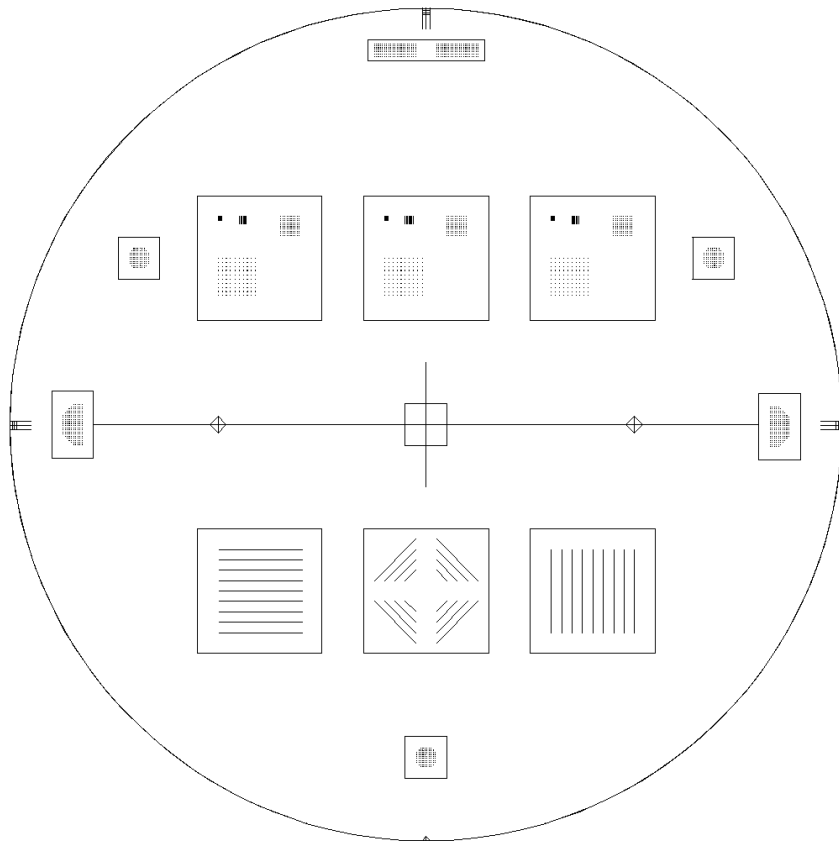
Size	140.3 μm	143.7 μm	150.4 μm	160.5 μm	184.9 μm	240.0 μm
Image						

- **Surface-Bump**

Size	102.2 μm	107.0 μm	111.5 μm	115.0 μm	120.3 μm	134.8 μm
Image						

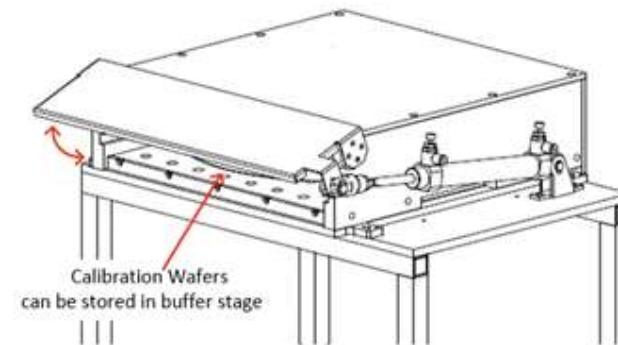
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Calibration wafer & Buffer Stage



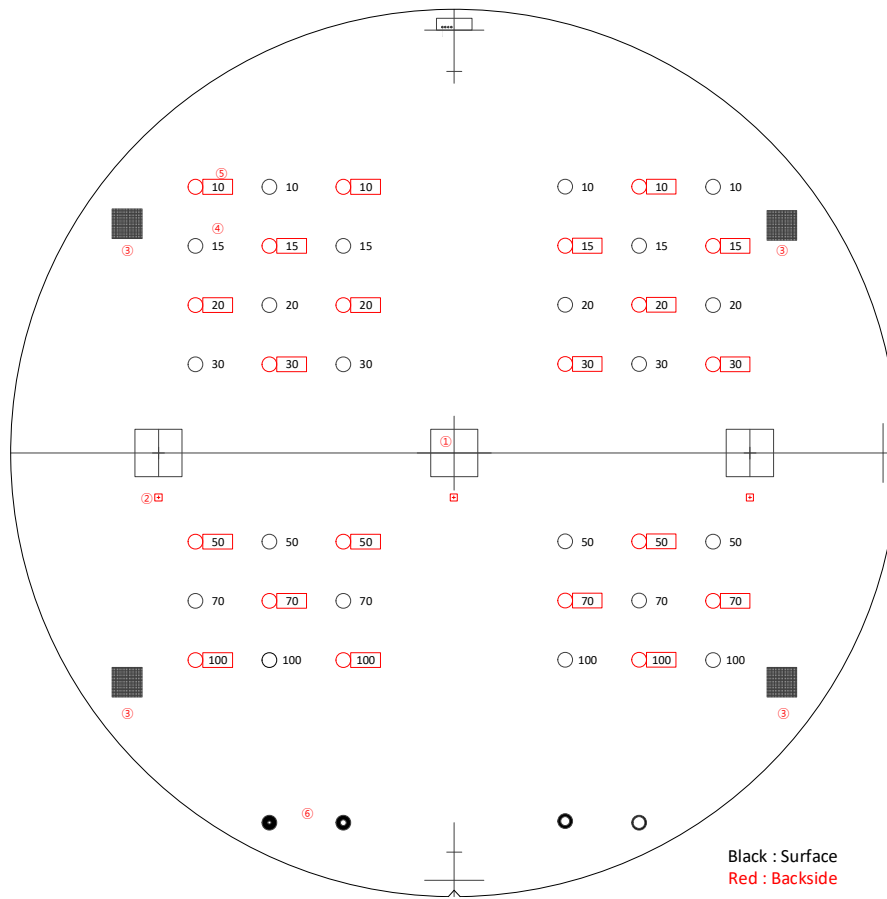
Fully automated setting process using the calibration wafer
=> quick and convenient setup.

- * Align vision system and inspection stage.
- * Defect detection function calibration.
- * Optimize light setting.

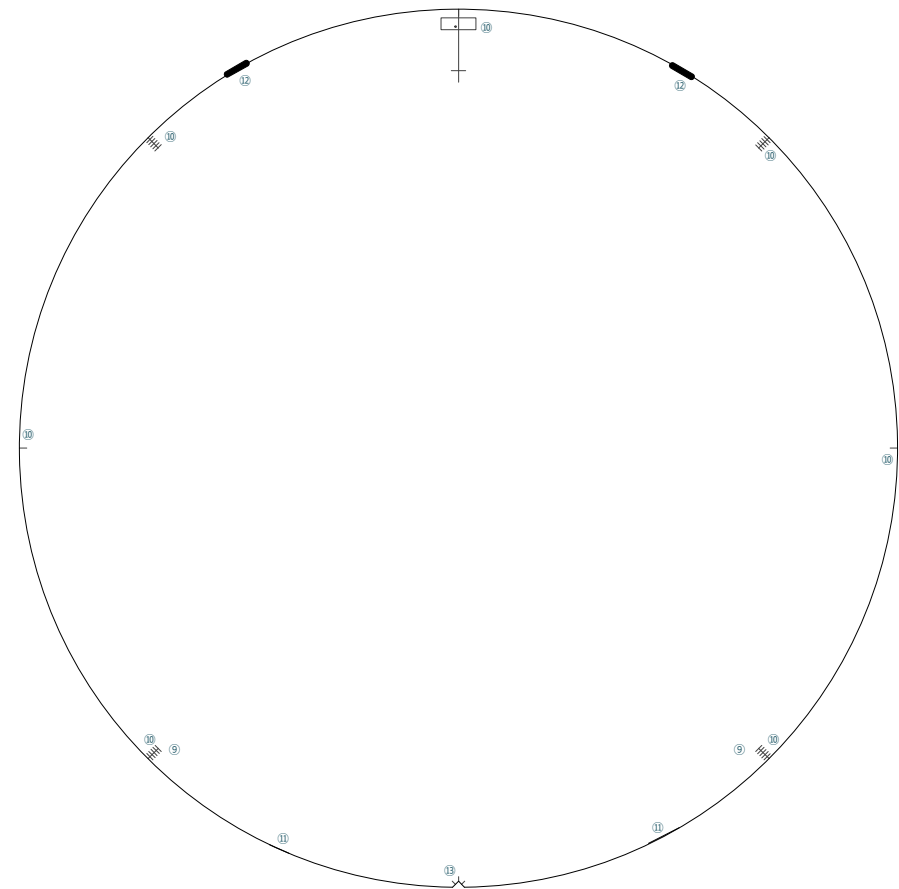


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IIM Calibration Wafer v4.00



EIS Calibration Wafer v1.00

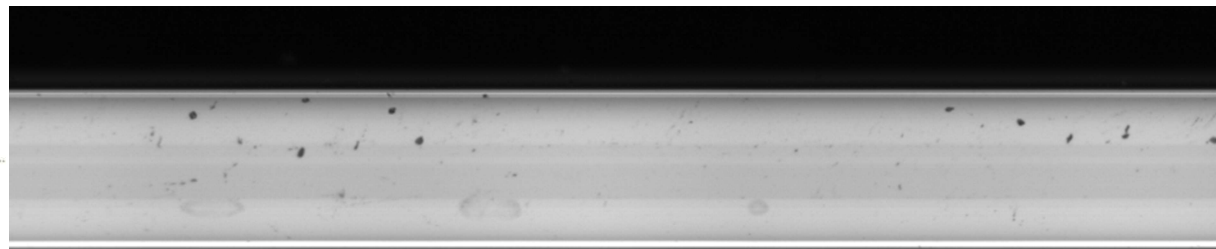
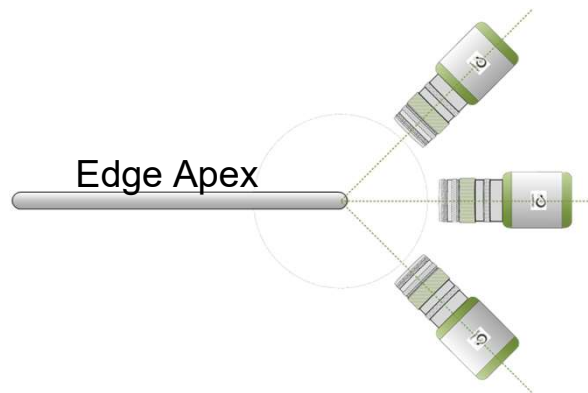
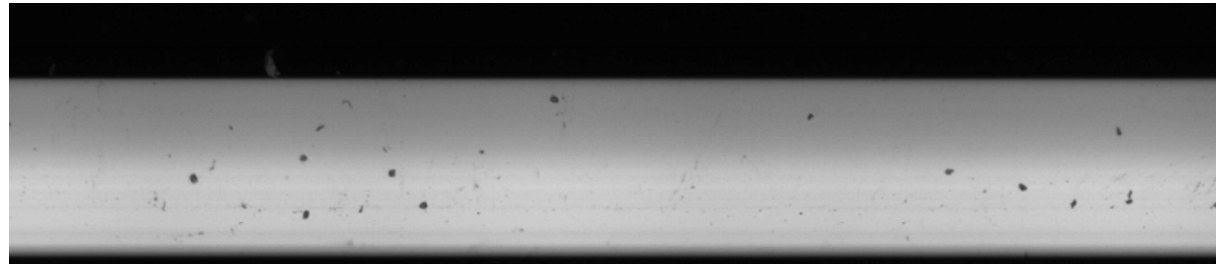


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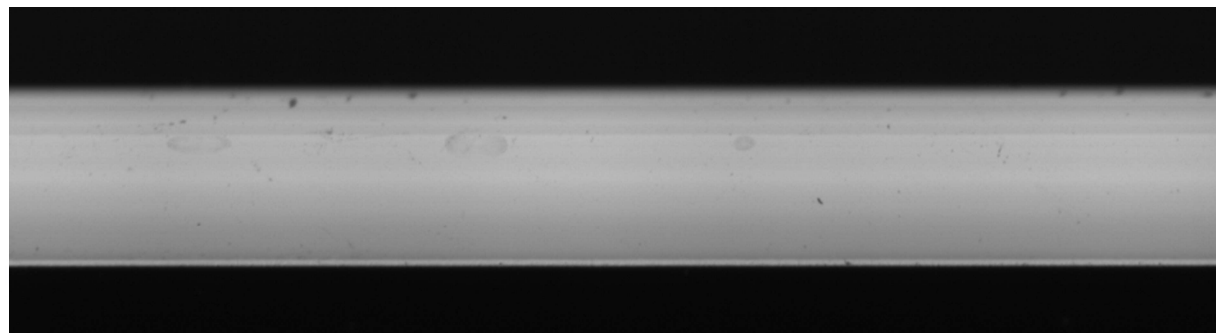
Edge Images A

Wafer Type 1 (Wide Bevel)

Edge Upper Bevel



Edge Lower Bevel

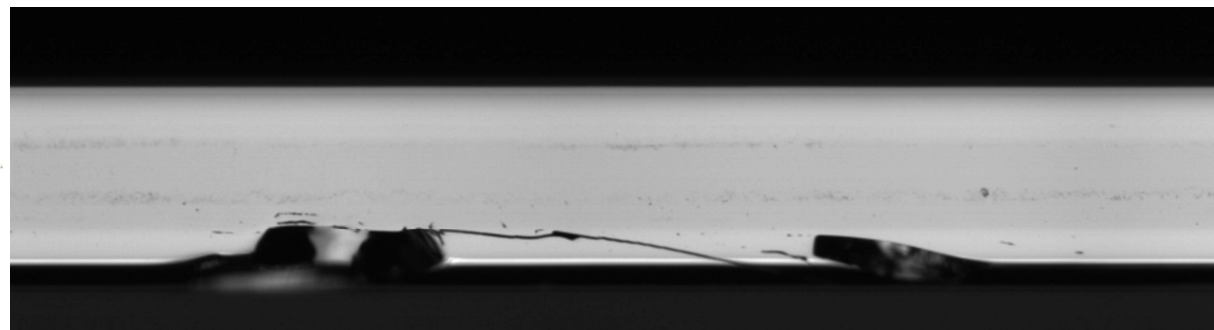
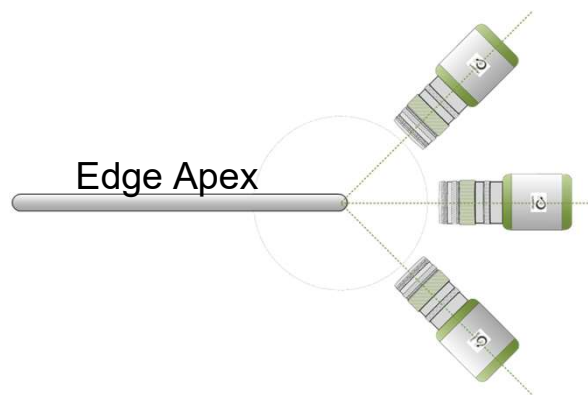
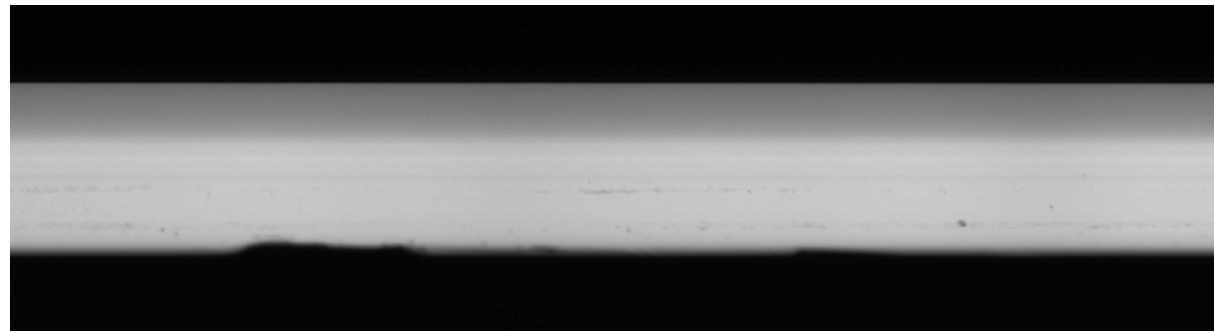


C

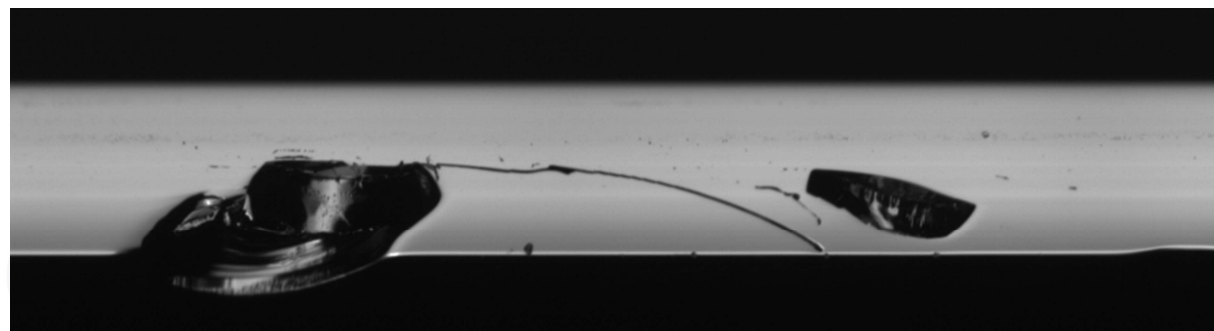
Edge Images B

Wafer Type 2 (Narrow Bevel)

Edge Upper Bevel



Edge Lower Bevel

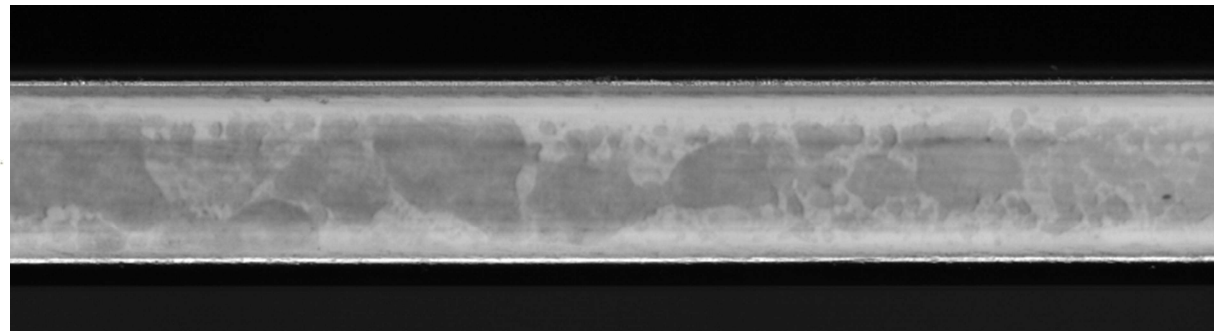
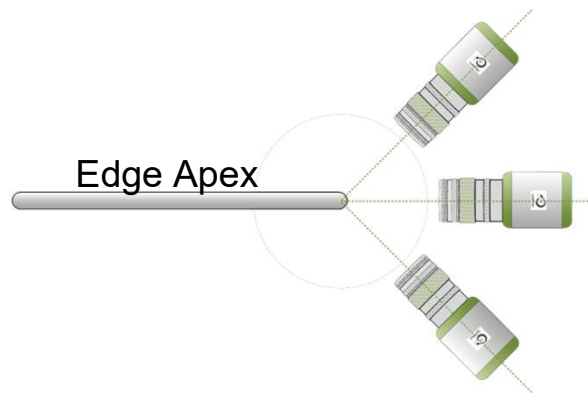
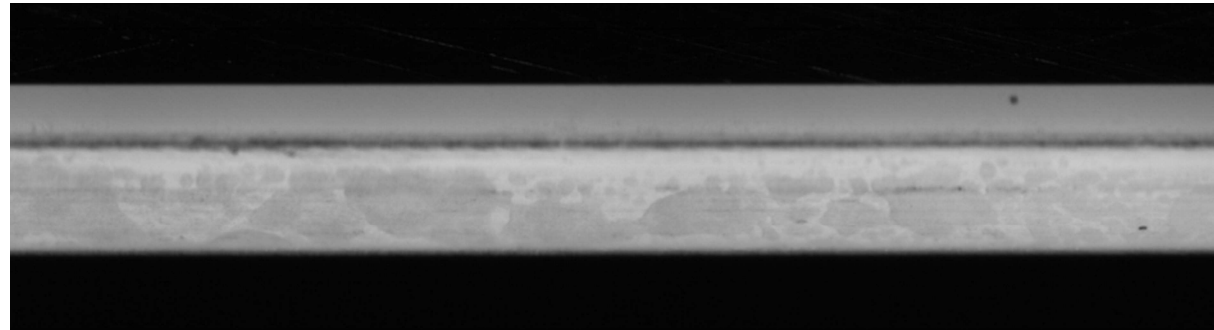


C

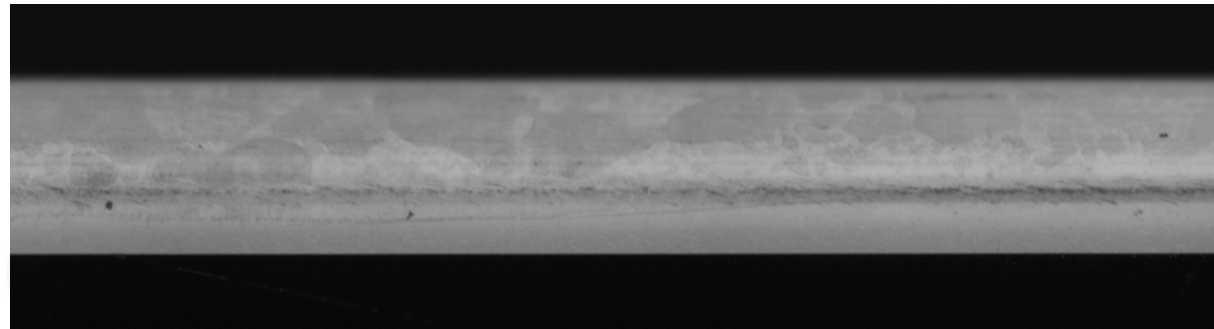
Edge Images C

Wafer Type 3 (Ground)

Edge Upper Bevel



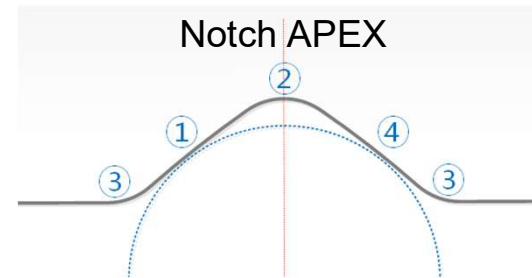
Edge Lower Bevel



C

Notch Images A

Wafer Type 1 (Wide Bevel)

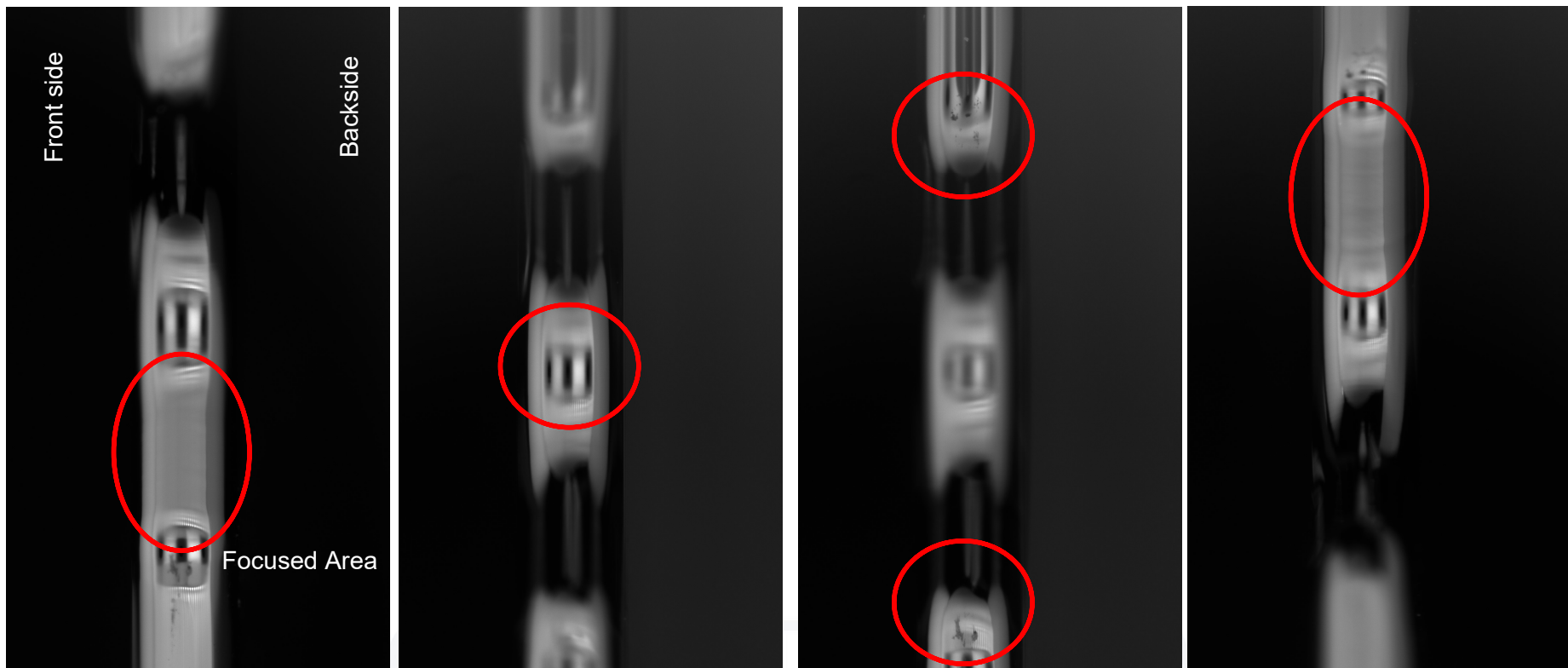


Left Shoulder of APEX
Focused ①

APEX Center
Focused ②

APEX Shoulder
Focused ③

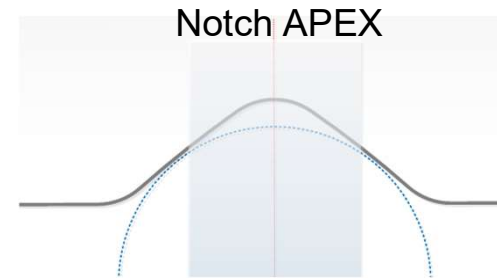
Right Shoulder of APEX
Focused ④



Notch Images A

Wafer Type 1 (Wide Bevel)

Notch APEX (Dark Field)

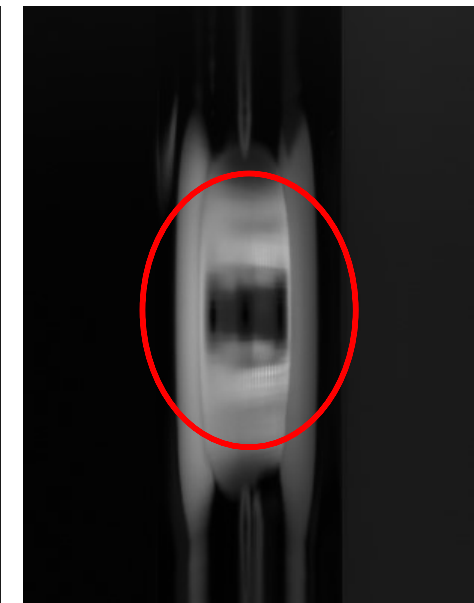
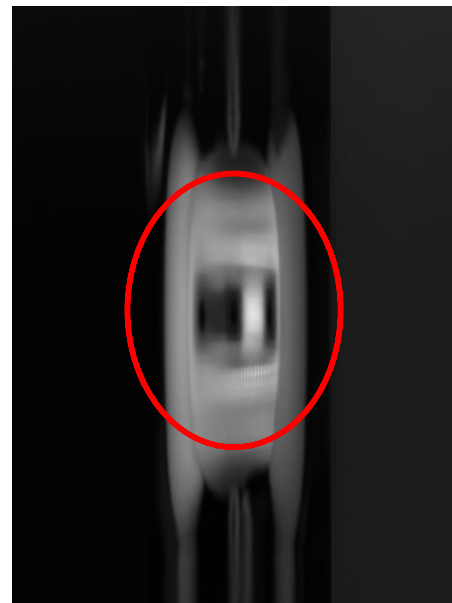
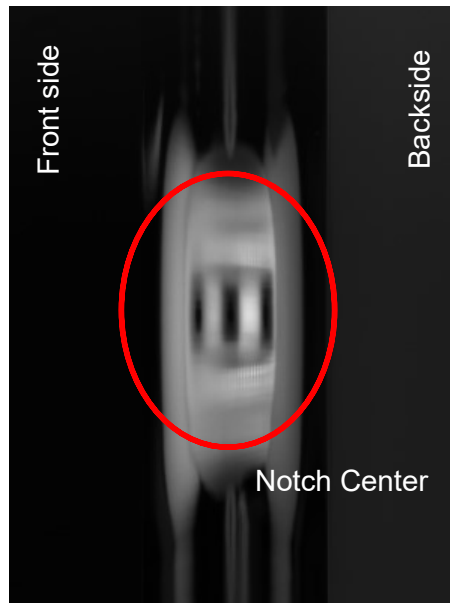


Dark Field
Condition 1

Dark Field
Condition 2

Dark Field
Condition 3

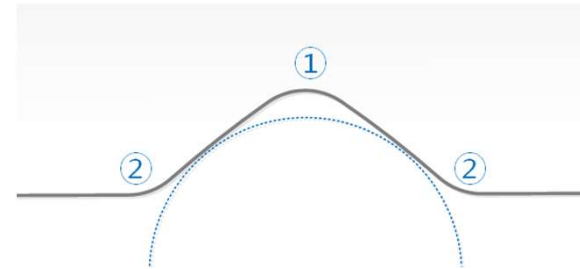
Dark Field
Condition 4



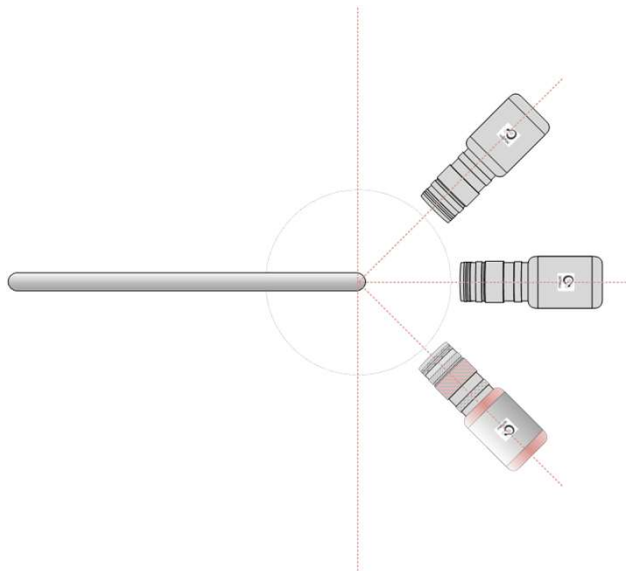
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Notch Images A

Wafer Type 1 (Wide Bevel)

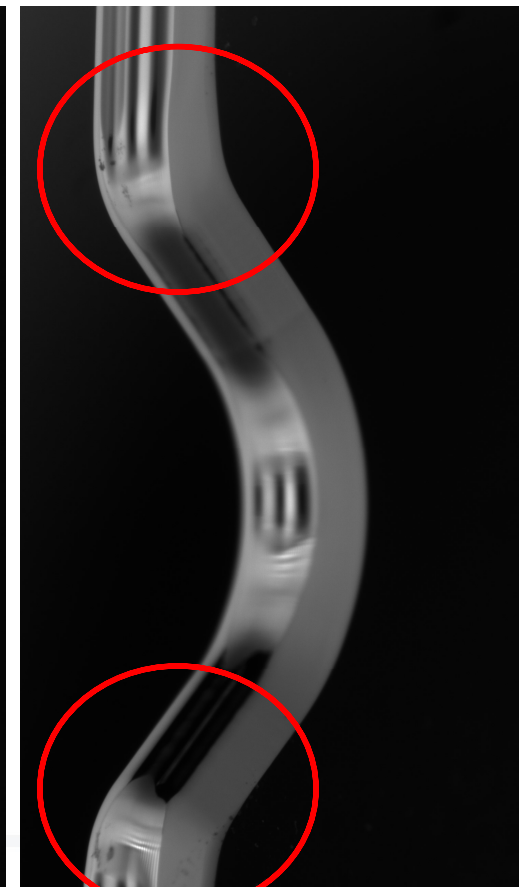
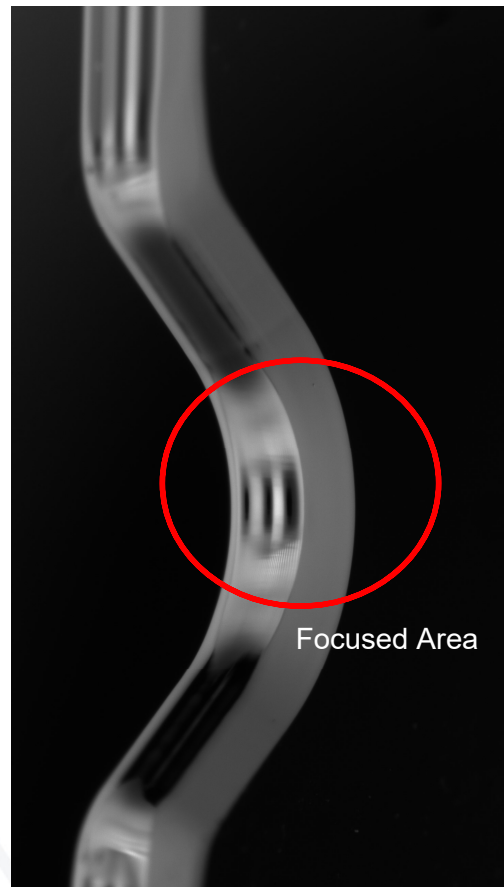


Notch Lower Bevel



Notch LB Center Focused ①

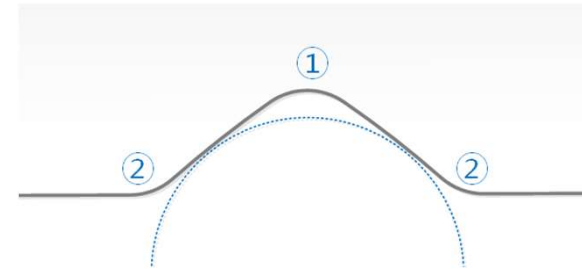
Notch LB Shoulder Focused ②



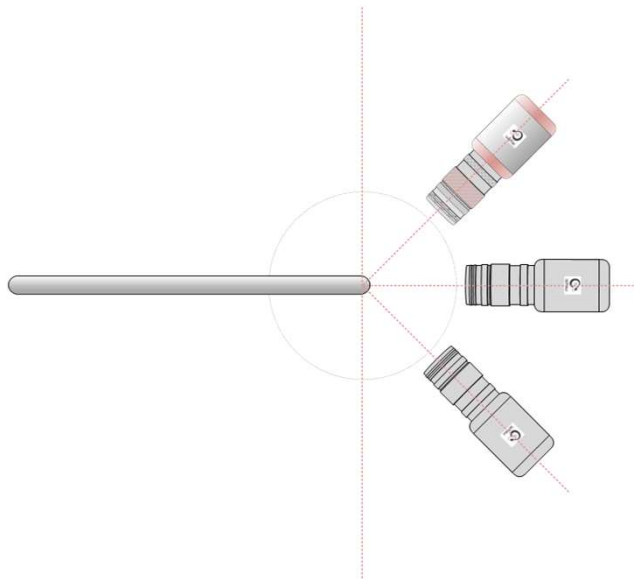
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Notch Images A

Wafer Type 1 (Wide Bevel)

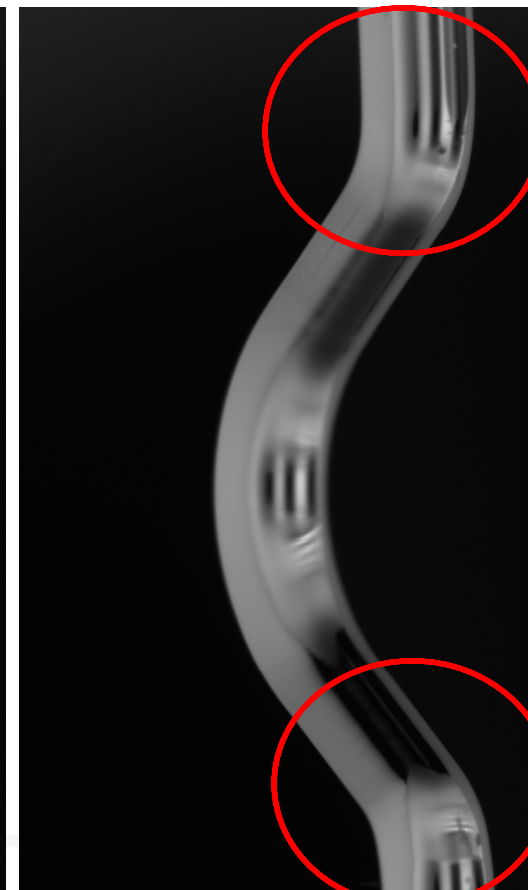
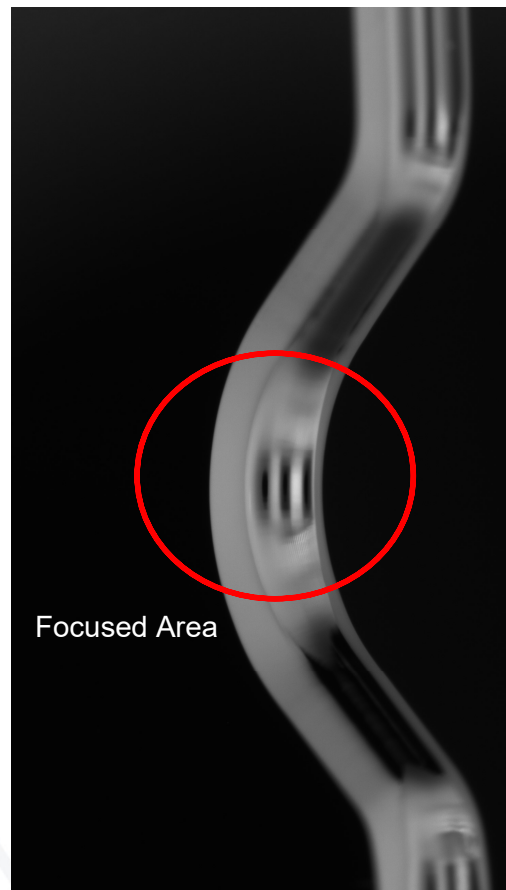


Notch Upper Bevel



Notch UB Center Focused ①

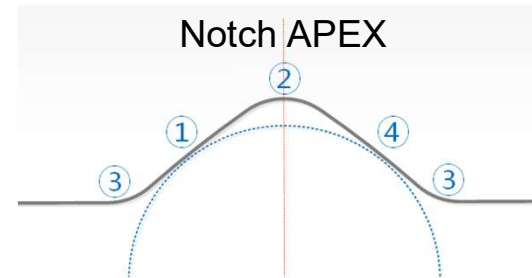
Notch UB Shoulder Focused ②



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Notch Images B

Wafer Type 2 (Narrow Bevel)

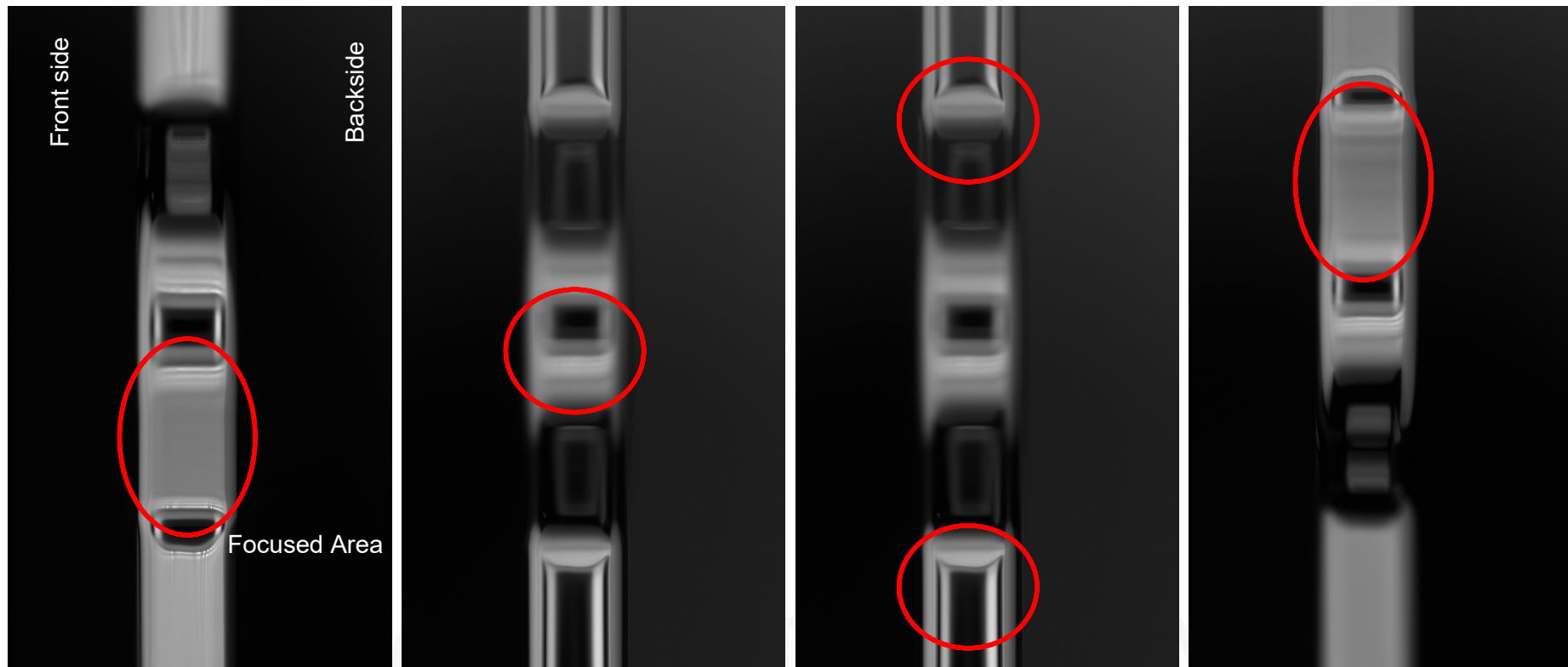


Left Shoulder of APEX
Focused ①

APEX Center
Focused ②

APEX Shoulder
Focused ③

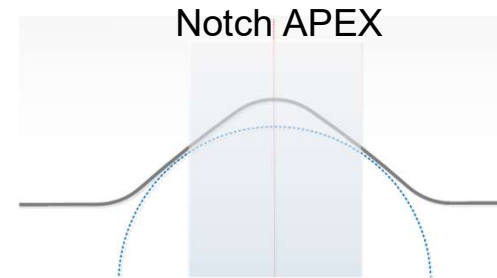
Right Shoulder of APEX
Focused ④



Notch Images B

Wafer Type 2 (Narrow Bevel)

Notch APEX (Dark Field)

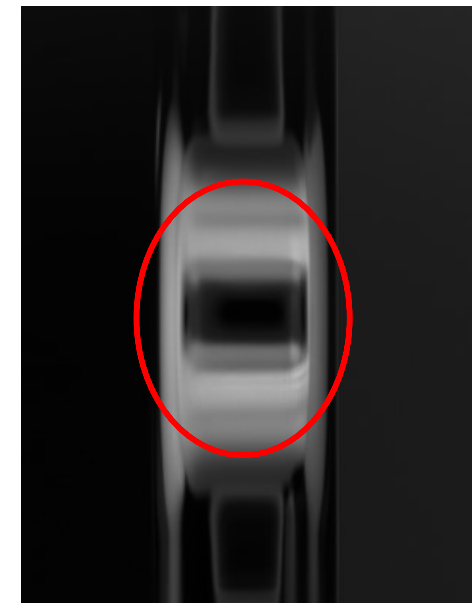
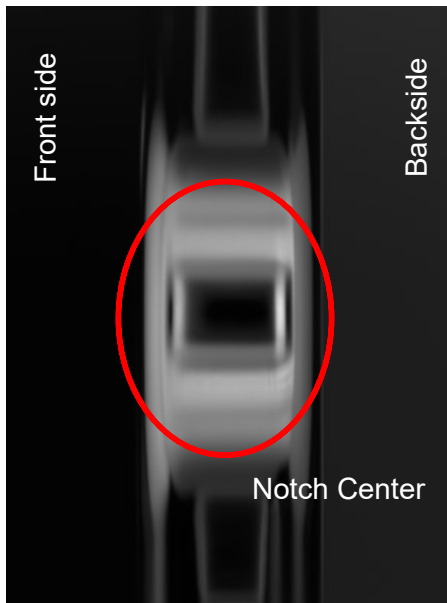


Dark Field
Condition 1

Dark Field
Condition 2

Dark Field
Condition 3

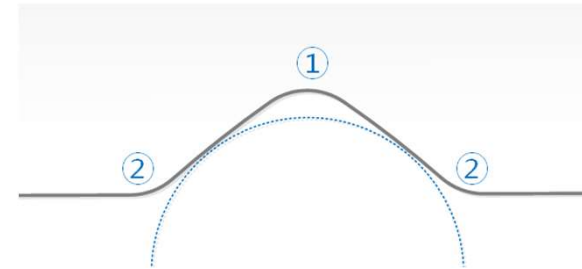
Dark Field
Condition 4



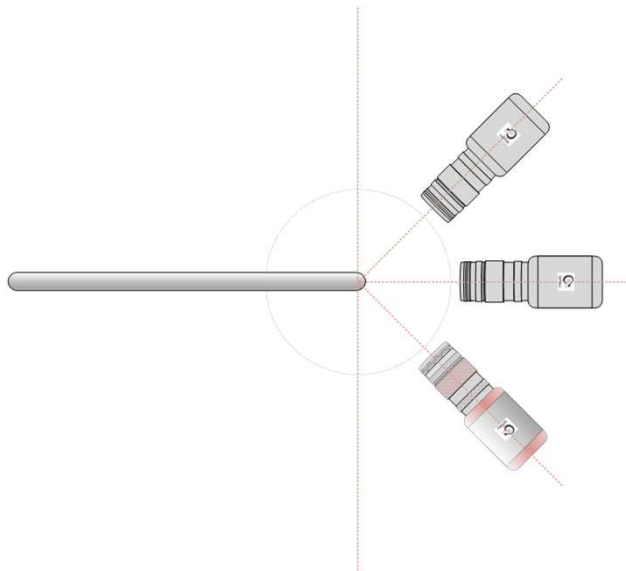
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Notch Images B

Wafer Type 2 (Narrow Bevel)

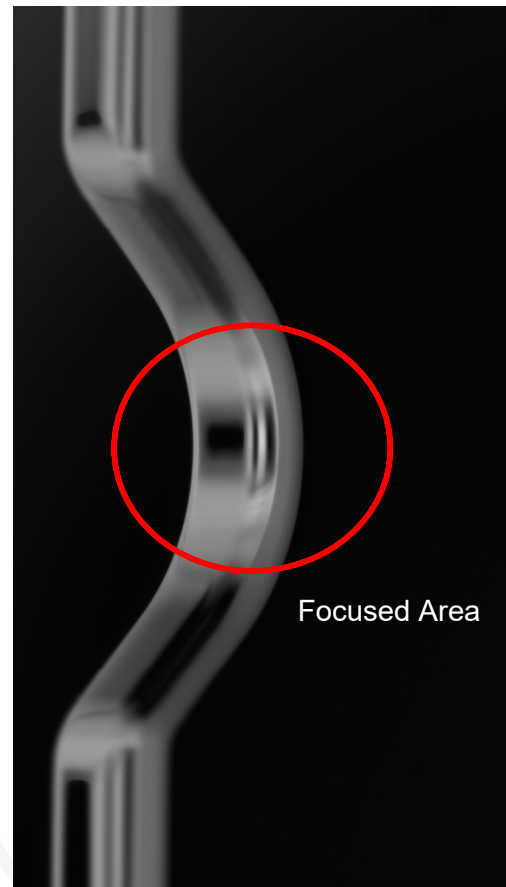


Notch Lower Bevel



Notch LB Center Focused ①

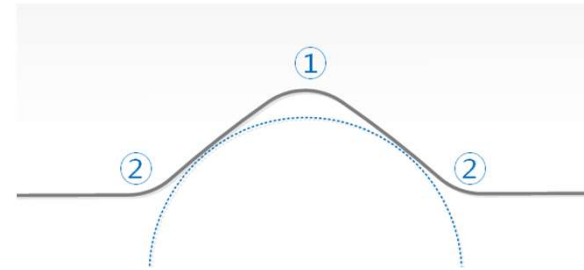
Notch LB Shoulder Focused ②



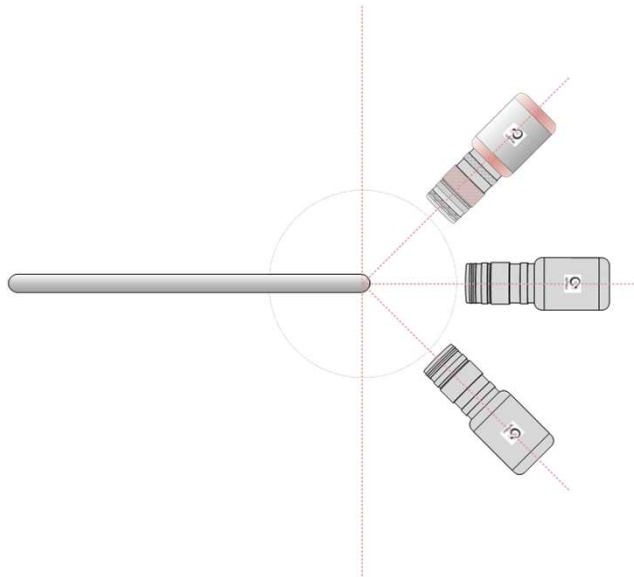
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Notch Images B

Wafer Type 2 (Narrow Bevel)

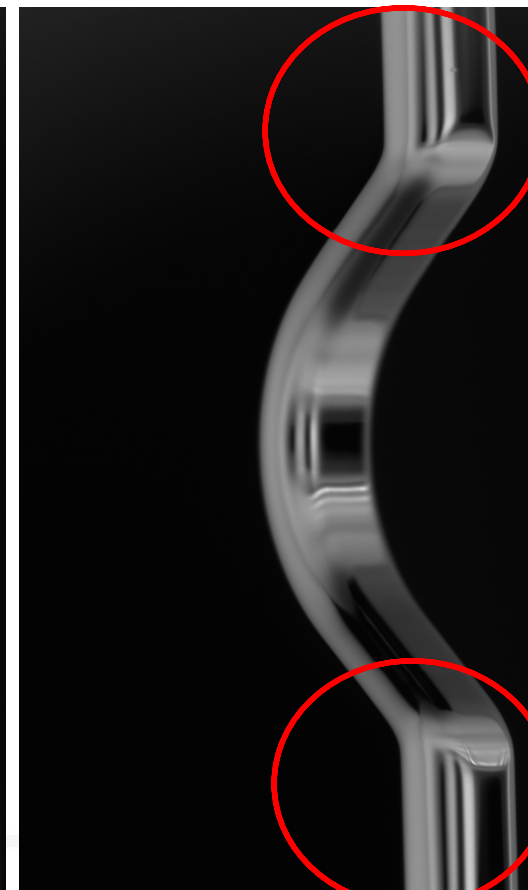
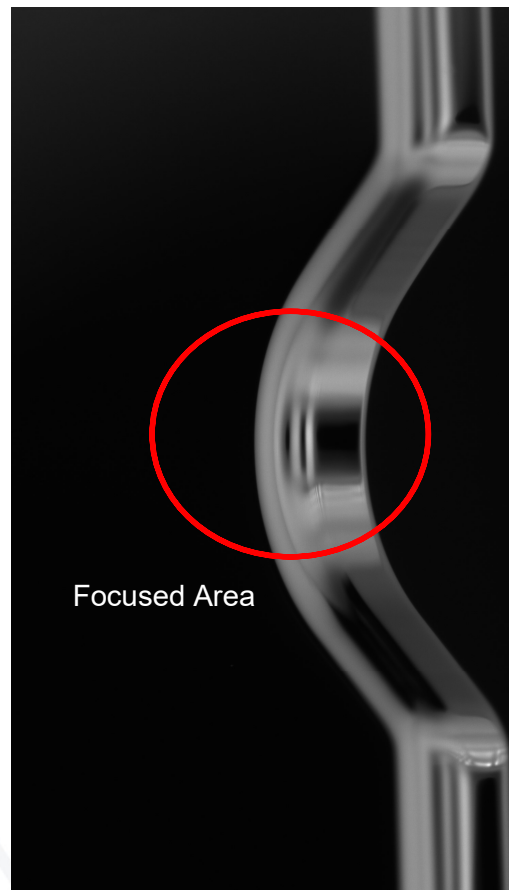


Notch Upper Bevel



Notch UB Center Focused ①

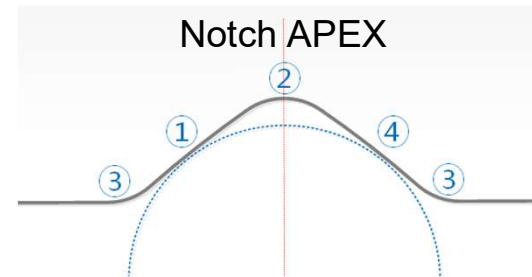
Notch UB Shoulder Focused ②



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Notch Images C

Wafer Type 3 (Ground Wafer)

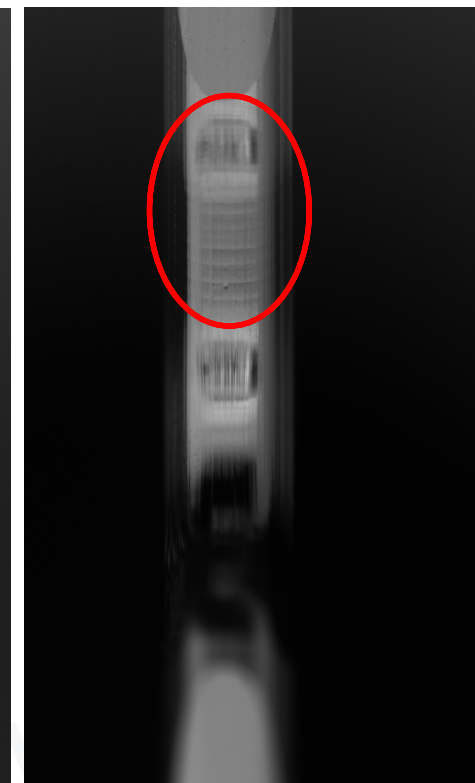
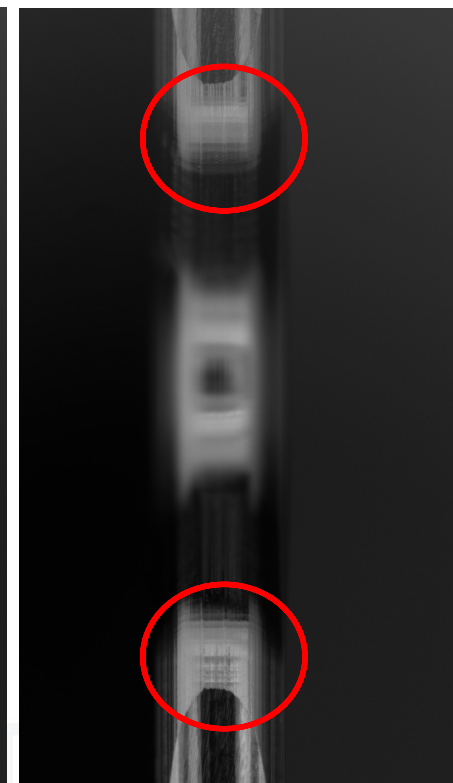
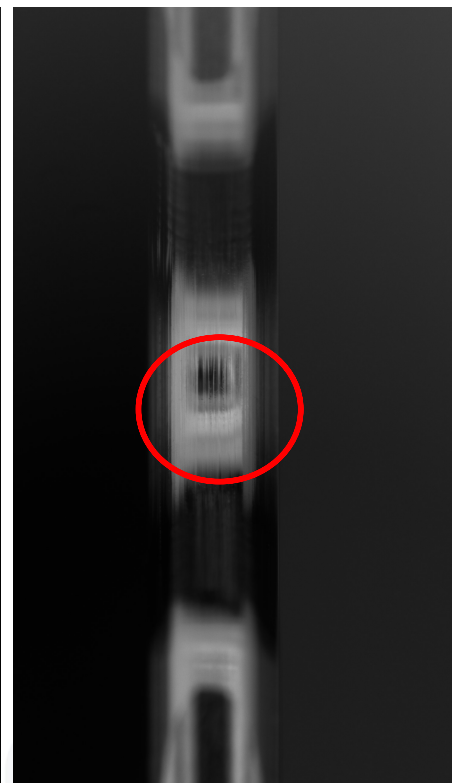
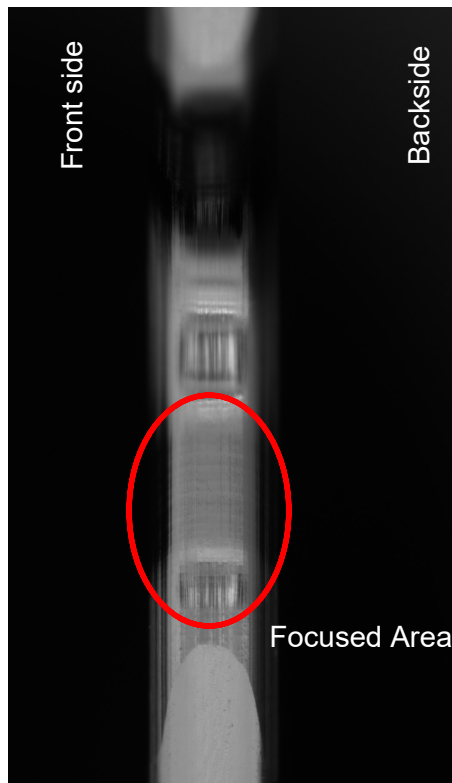


Left Shoulder of APEX
Focused ①

APEX Center
Focused ②

APEX Shoulder
Focused ③

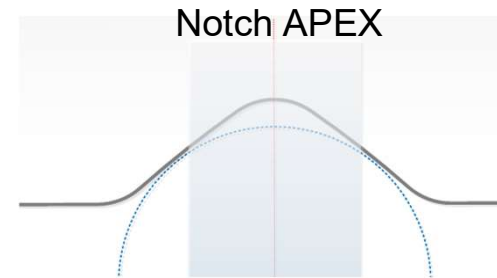
Right Shoulder of APEX
Focused ④



Notch Images C

Wafer Type 3 (Ground Wafer)

Notch APEX (Dark Field)

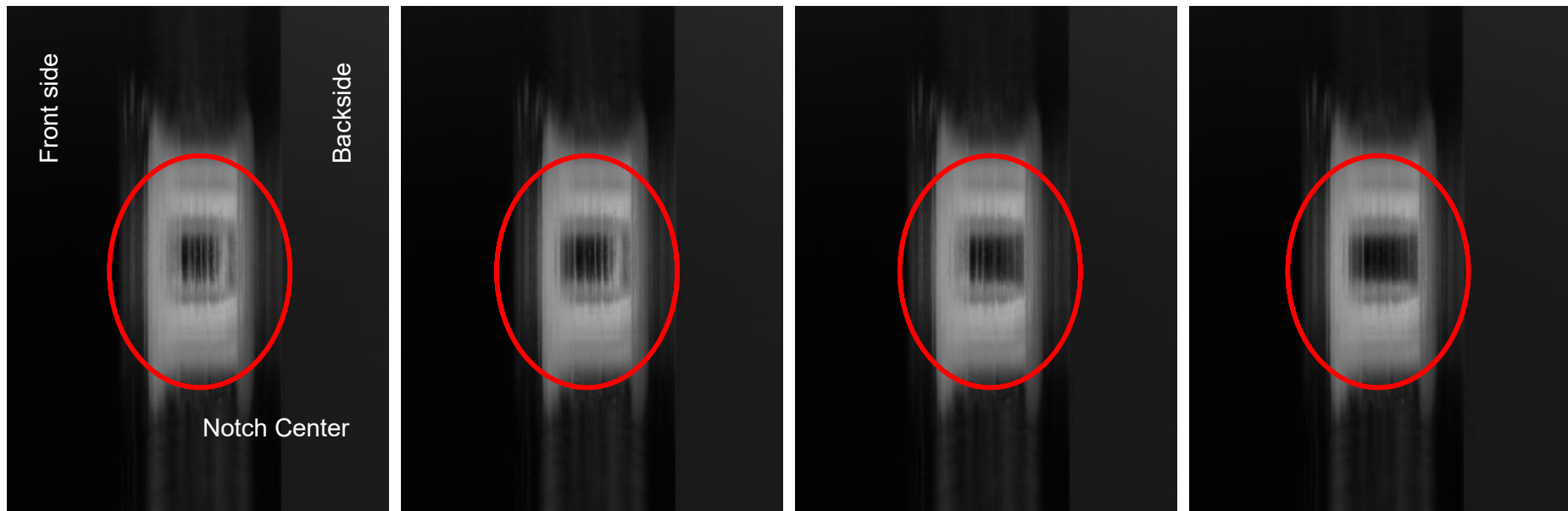


Dark Field
Condition 1

Dark Field
Condition 2

Dark Field
Condition 3

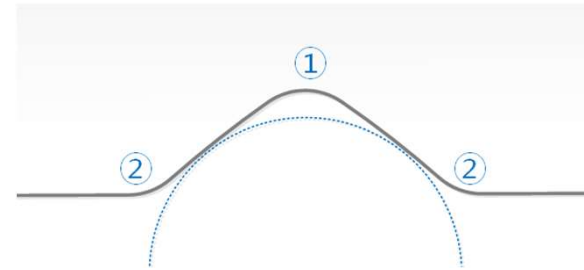
Dark Field
Condition 4



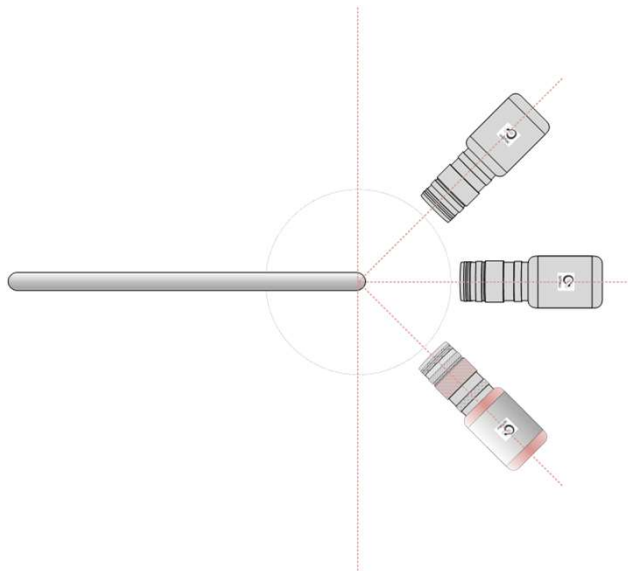
CONFIDENTIAL

Notch Images C

Wafer Type 3 (Ground Wafer)

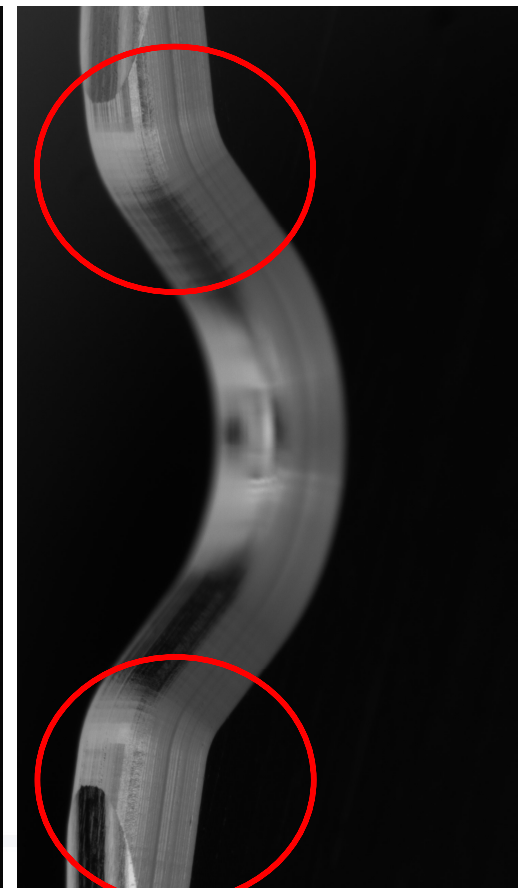
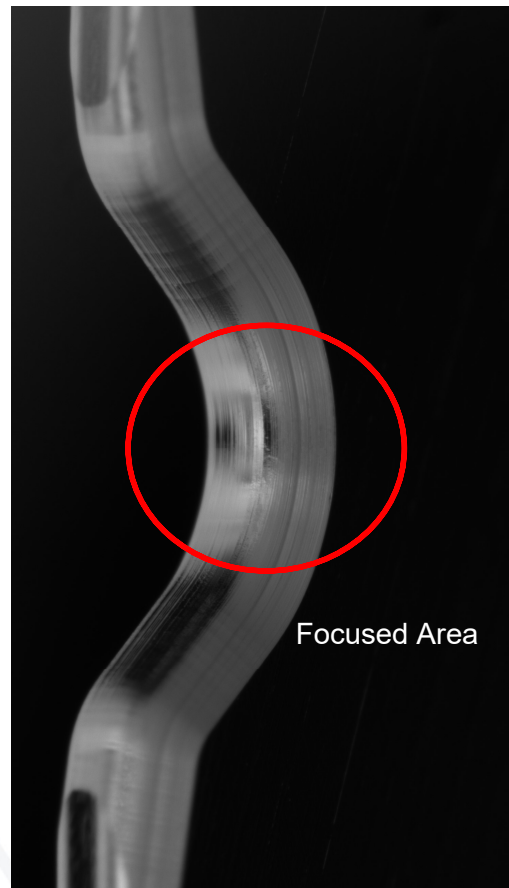


Notch Lower Bevel



Notch LB Center Focused ①

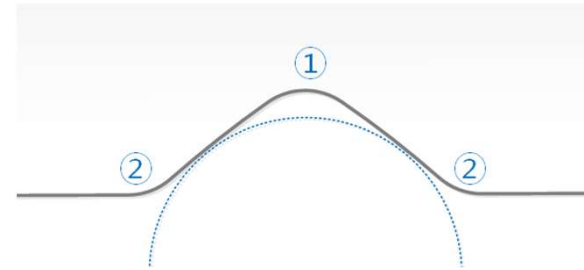
Notch LB Shoulder Focused ②



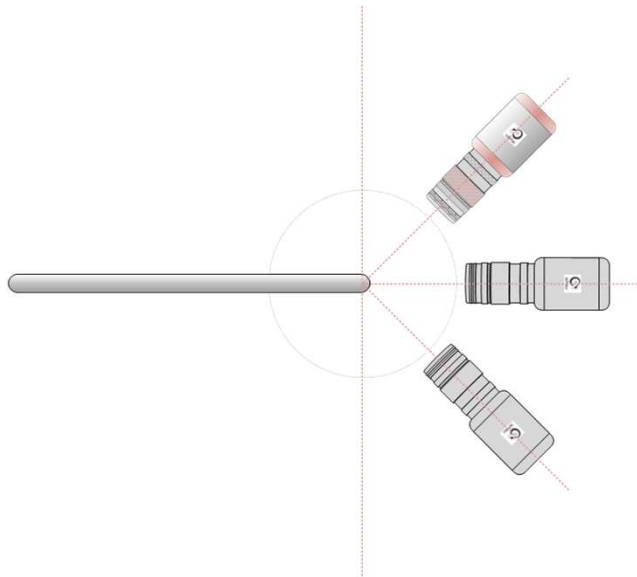
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Notch Images C

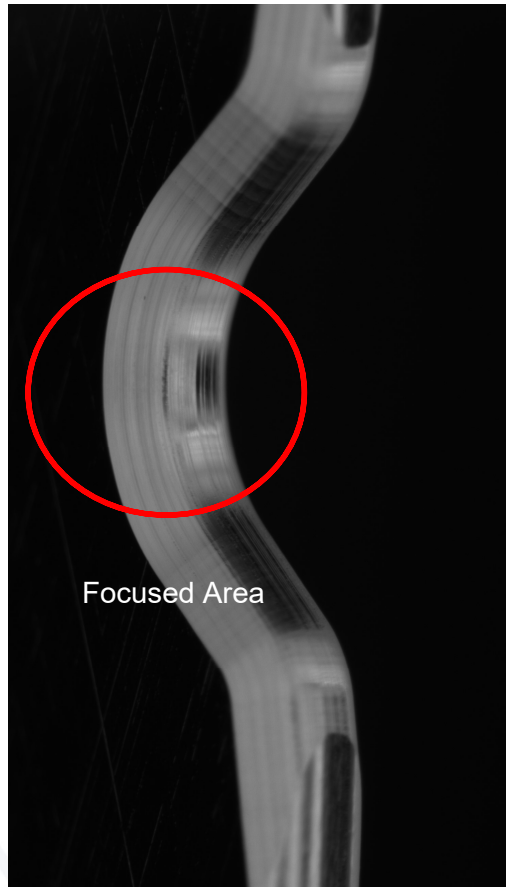
Wafer Type 3 (Ground Wafer)



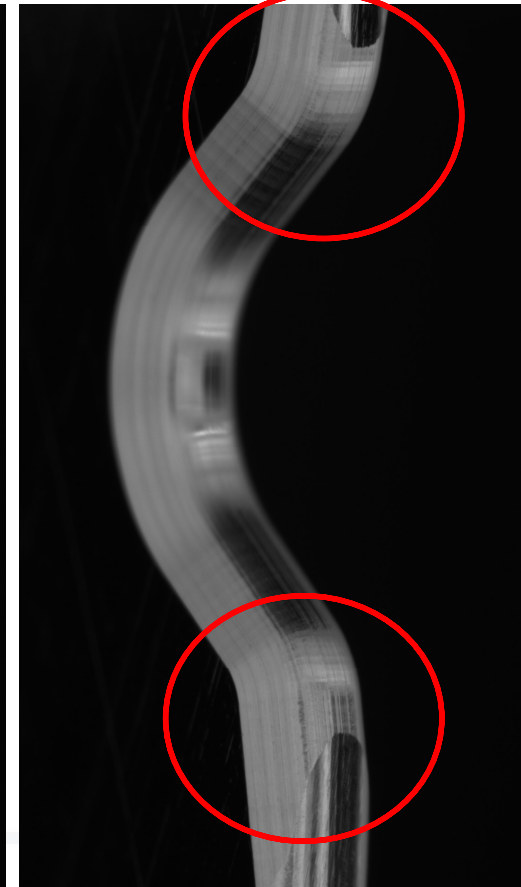
Notch Upper Bevel



Notch UB Center Focused ①



Notch UB Shoulder Focused ②



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Throughput

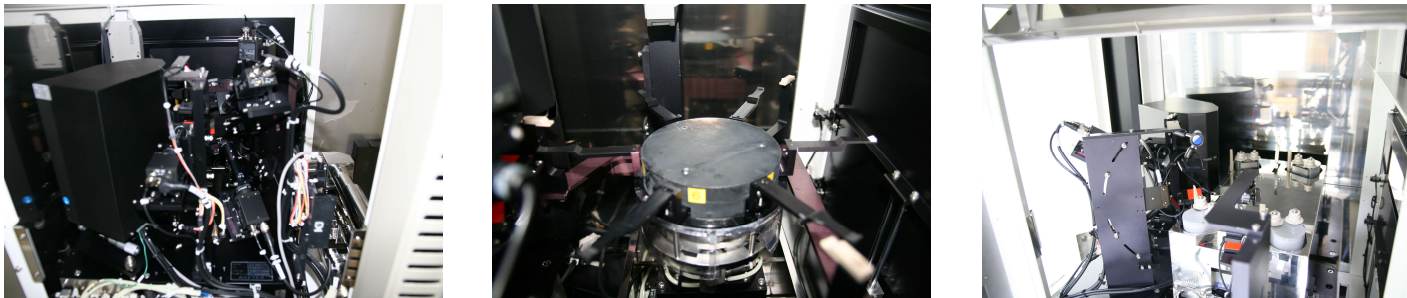
Edge					Notch			Back Side	Front Side			T/P (sec/wafer)	T/P (wafer/h)
Apex	Upper Bevel	Lower Bevel	Edge Top	Edge Bottom	Apex	Upper Bevel	Lower Bevel		Dark Field	Bright Field	Pit		
○	○	○									40	90	
○	○	○	○	○							40	90	
○	○	○			○	○	○				40	90	
○	○	○	○	○	○	○	○				40	90	
○	○	○						○			43	83	
○	○	○	○	○				○			43	83	
○	○	○			○	○	○	○			43	83	
○	○	○	○	○	○	○	○	○			43	83	
○	○	○						○	○	○	43	83	
○	○	○	○	○				○	○	○	43	83	
○	○	○			○	○	○	○	○	○	43	83	
○	○	○	○	○				○	○	○	45	80	
○	○	○	○	○				○	○	○	45	80	
○	○	○			○	○	○	○	○	○	45	80	
○	○	○	○	○	○	○	○	○	○	○	45	80	

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Comparision

Edge Optics



Two rotations of the edge scan is required to scan edge grip area. It is difficult to set up and maintenance because **five cameras and illuminations** are installed separately.

Difficulty classifying defects due to low camera specifications and laser scan method.

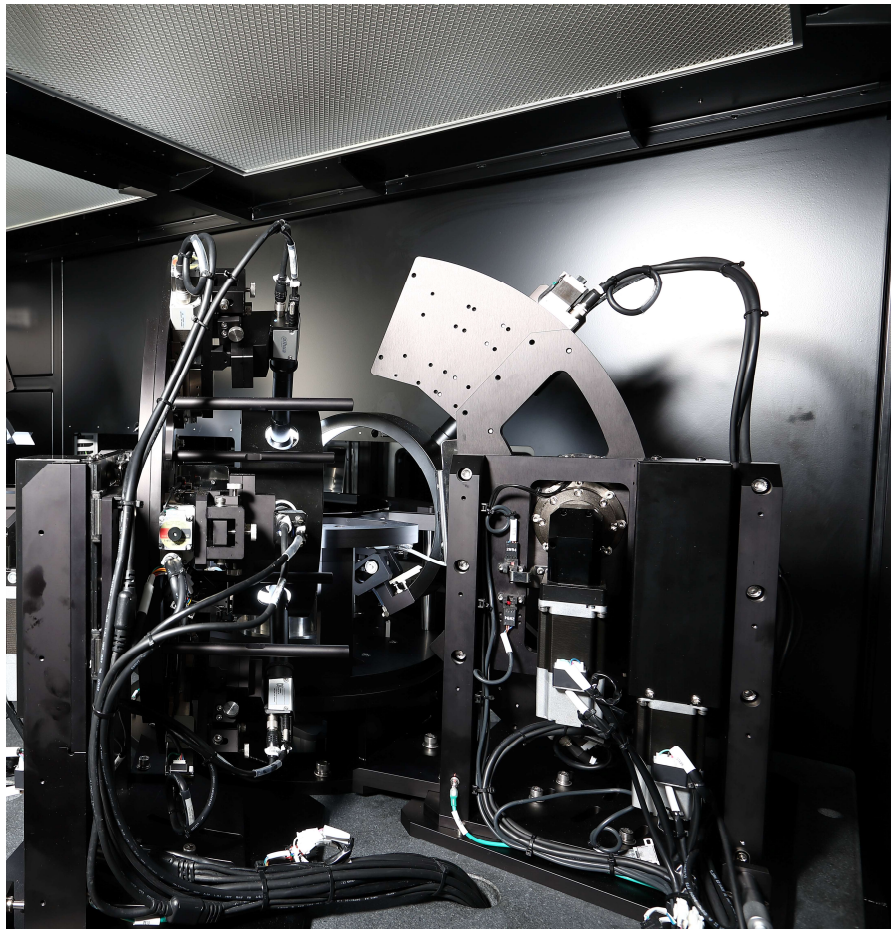
Auto Focusing Function is not supported.

Long time setup and Non-uniform performance between equipment because there is no **Edge calibration wafer**.

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COMIZOA

Edge Optics



Singe Turn Edge Inspection by using Dynamic folding edge grip fingers.

The **High Uniformity** between the five camera image sensors **Sensitivity**.

Setup and maintenance are easy with the **automatic focusing and automatic alignment function** of the camera unit.

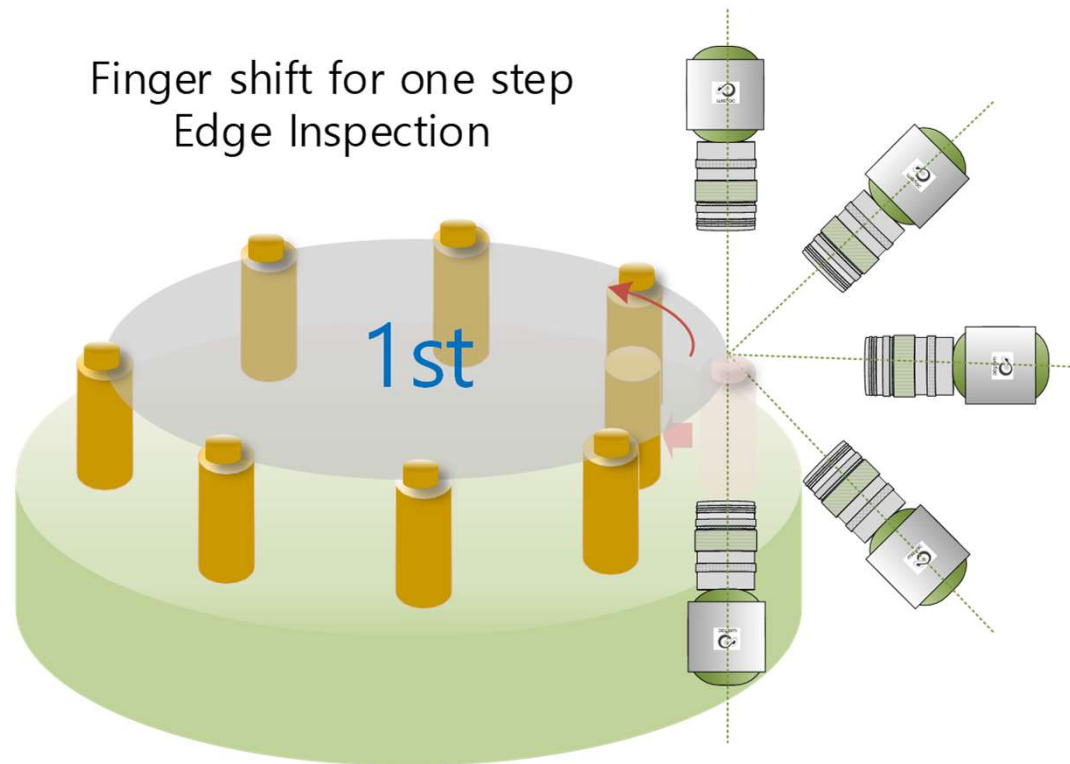
Combined illumination unit.

Edge damage and pollution risk are minimized by optimized contact area.

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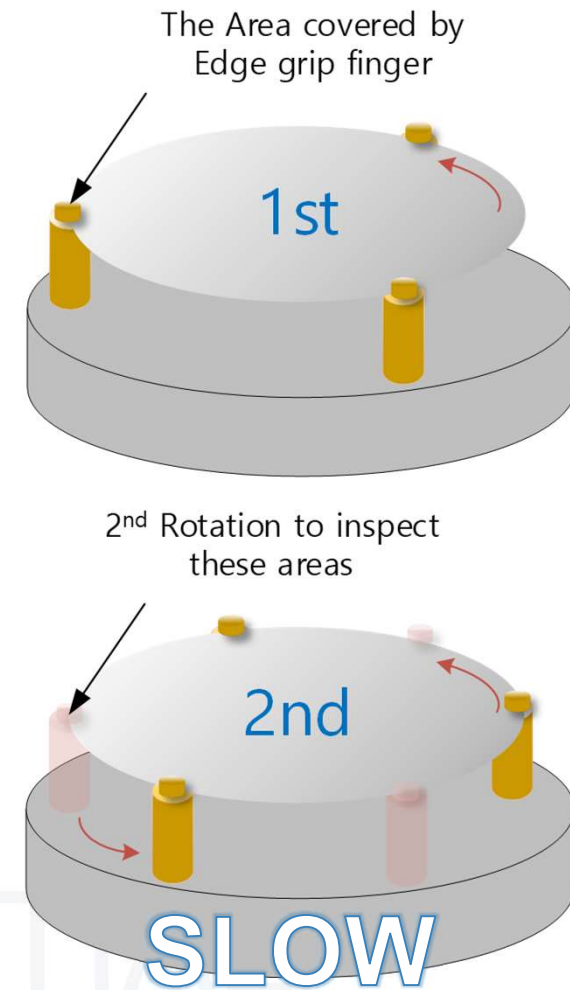
Edge Optics

COMIZOA single step



FAST

A company double step



SLOW

A company

Notch Optics

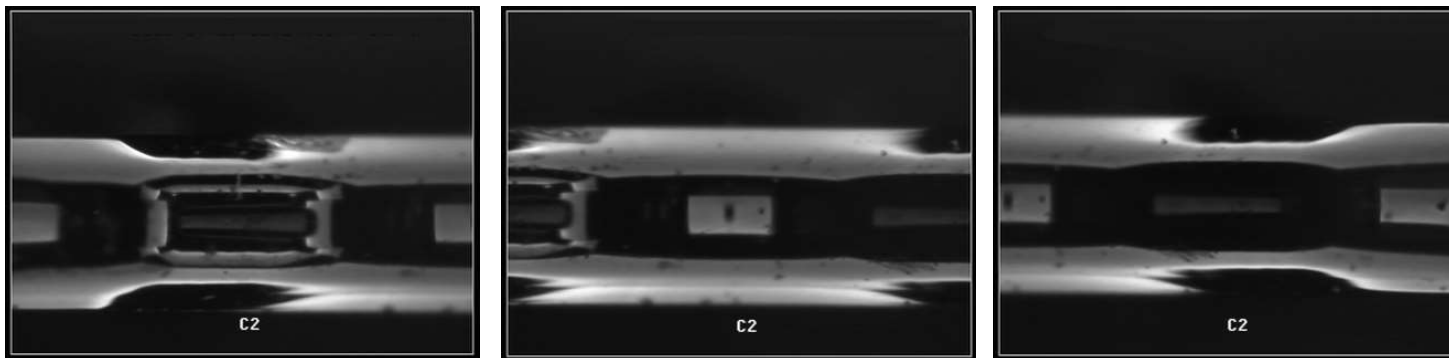
Only One Apex Camera – Area camera

There are no scan cameras for **Upper bevel** area and **Lower bevel** area.

Auto Focusing Function is not supported.

Long time setup and **Non-uniform performance** between equipment because there is **No Calibration wafer**.

No Upper Bevel Image



Left Shoulder of APEX

APEX Center

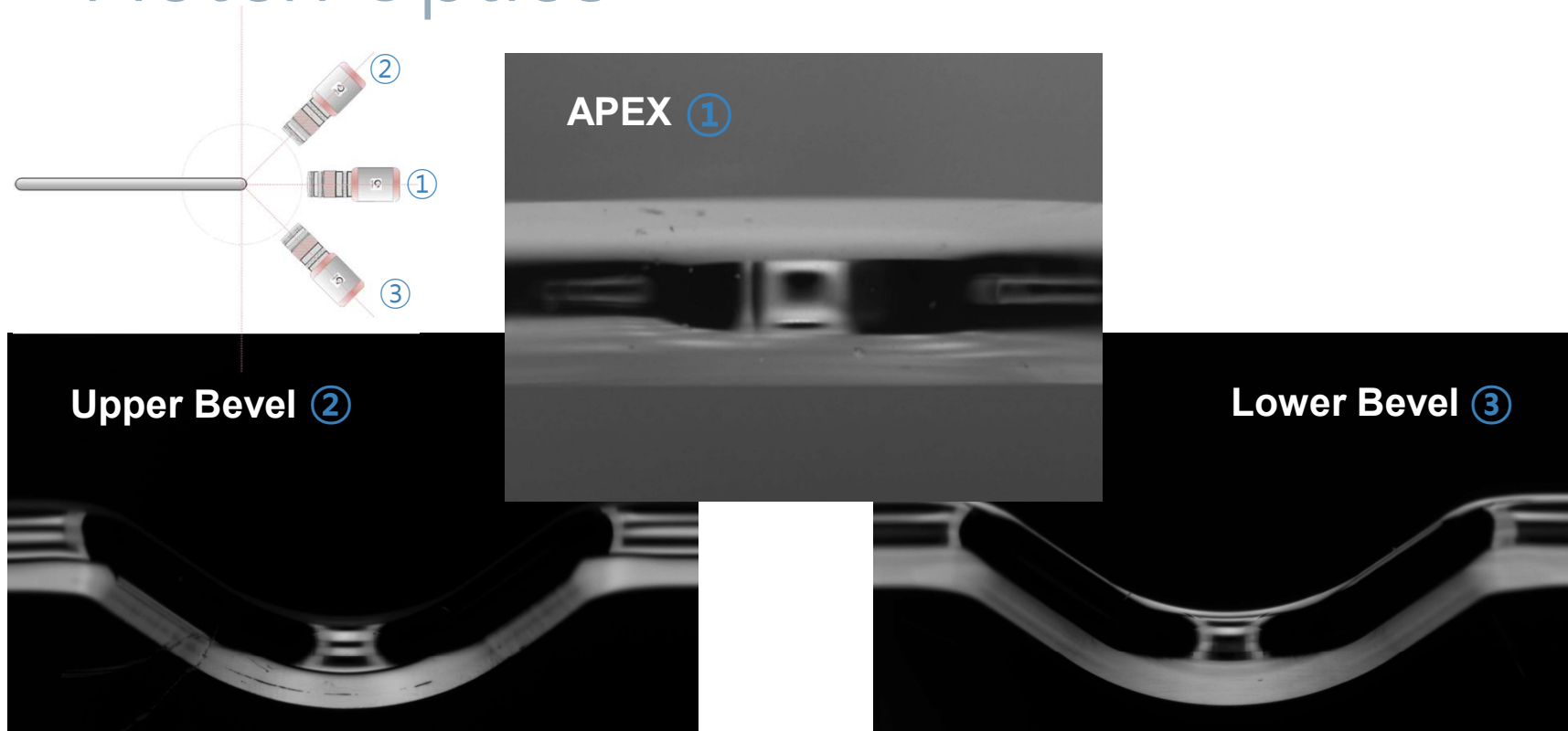
Right Shoulder of APEX

No Lower Bevel Image

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COMIZOA

Notch Optics



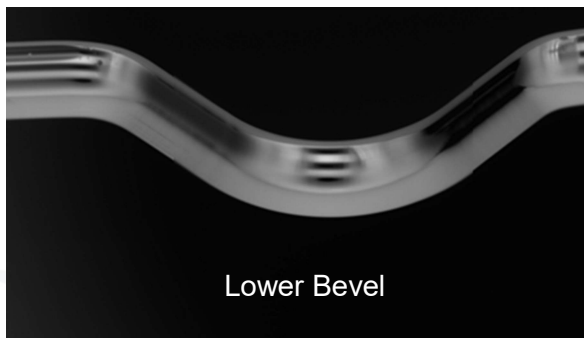
Three Notch Cameras are used for Upper bevel, Apex, Lower bevel.

Auto Focusing Function is supported for High quality image acquisition.

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COMIZOA

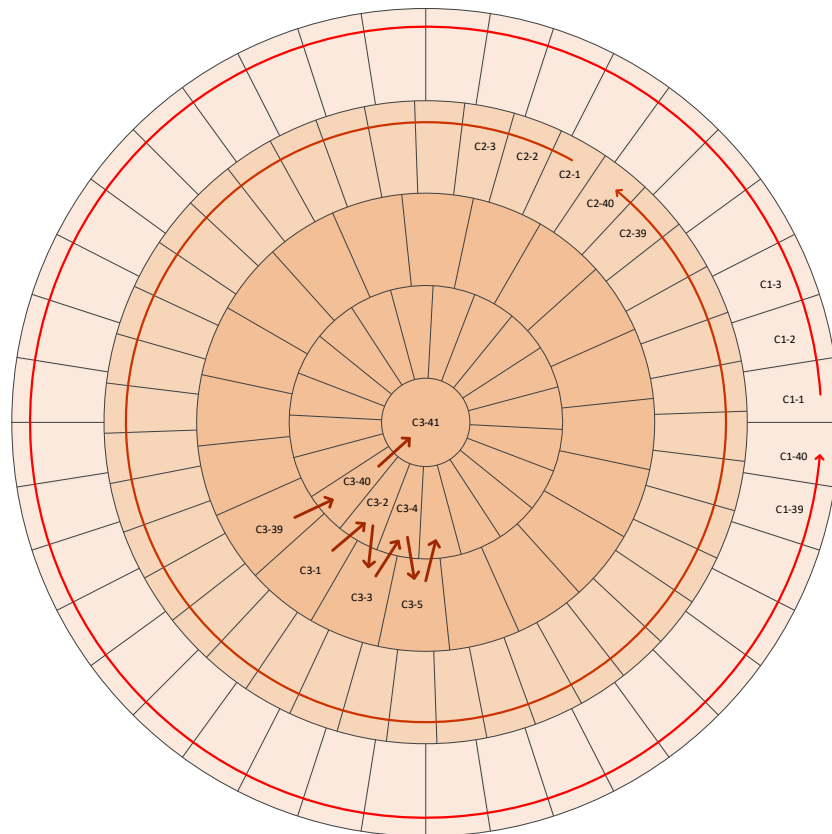
Notch Optics



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Back & Front side Inspection



3 Area Scan Cameras used.

- FOV : 38.5mm x 29mm

- C1 is fixed, and C2 and C3 can move in a straight line.

- C1 area : The outermost track of wafer (40 shots)
- C2 area : The middle track of wafer (40 shots)
- C3 area : The center of wafer (41 shots)

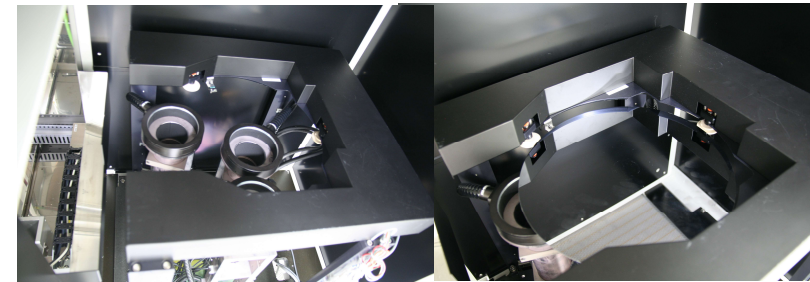
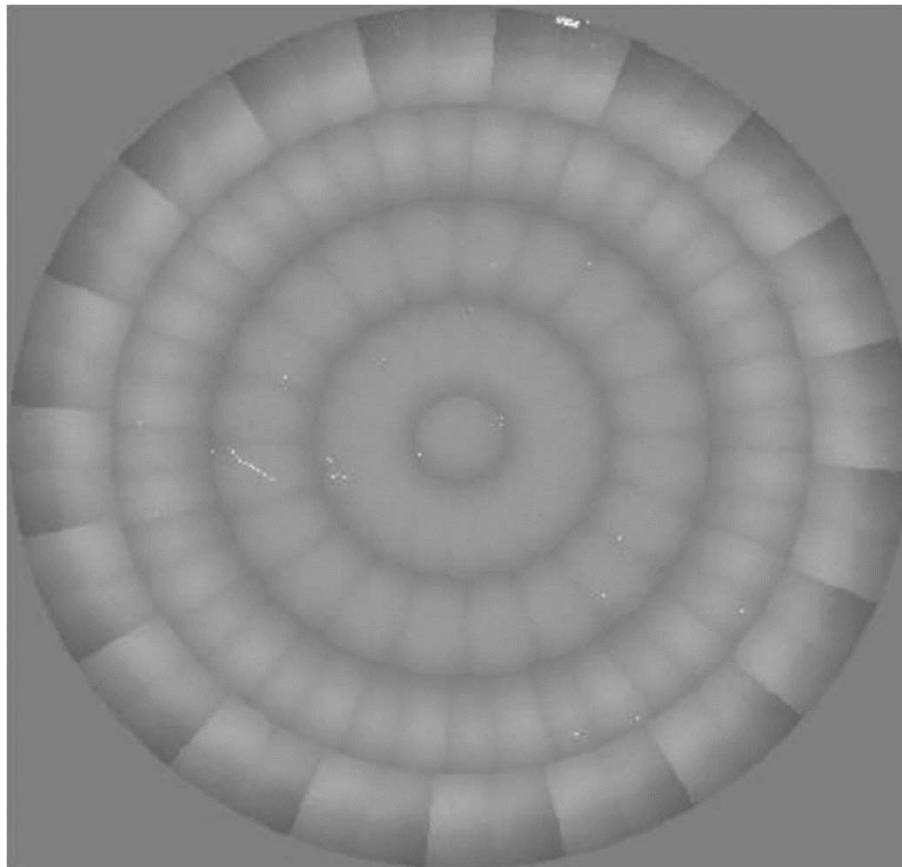
- Rotates the wafer 9 degrees and shoots per each step, a total of 40 images have gathered.

- C3 moves back and forth while shooting 40 shots, and finally shoots one shot for the wafer center.

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Back & Front side Inspection



The **imbalance** between the three camera image sensor's **Sensitivity**.

Image quality **deterioration** due to overlapping images.

Difficulties in camera setup and maintenance caused by using 3 area scan cameras.

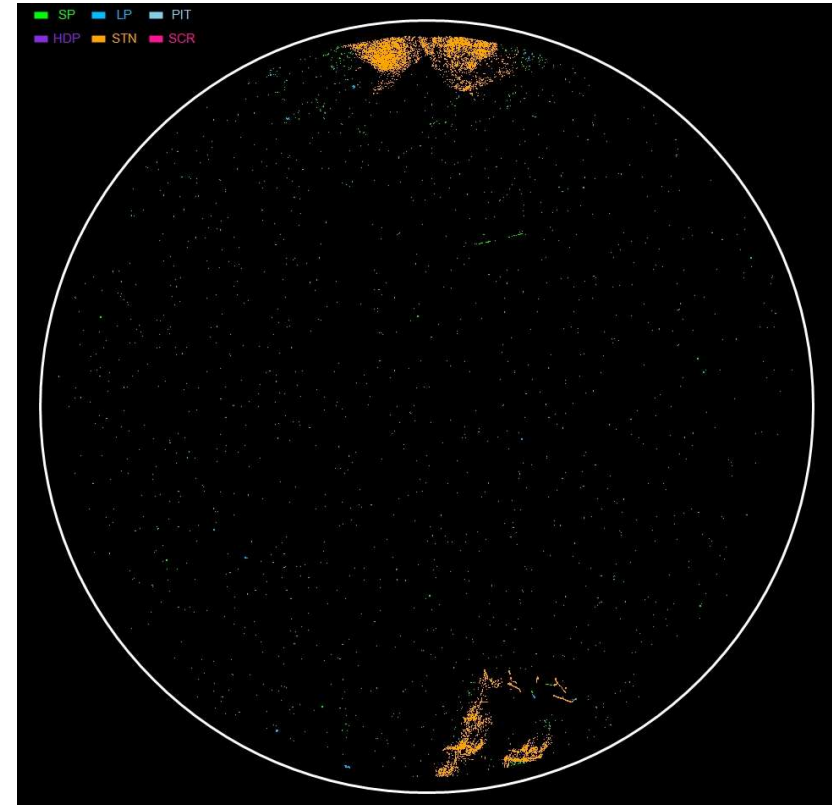
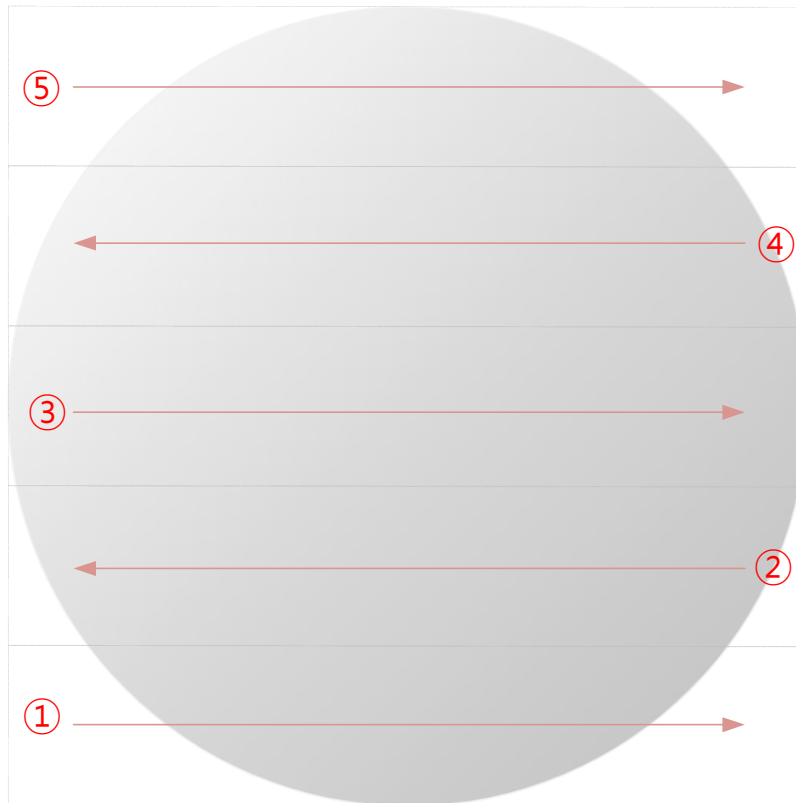
Performance deviation between equipment because there is no **calibration wafer**.

Risk of Edge damage and contamination caused by using a roller to rotate the wafer.

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COMIZOA 300mm

Back side Inspection



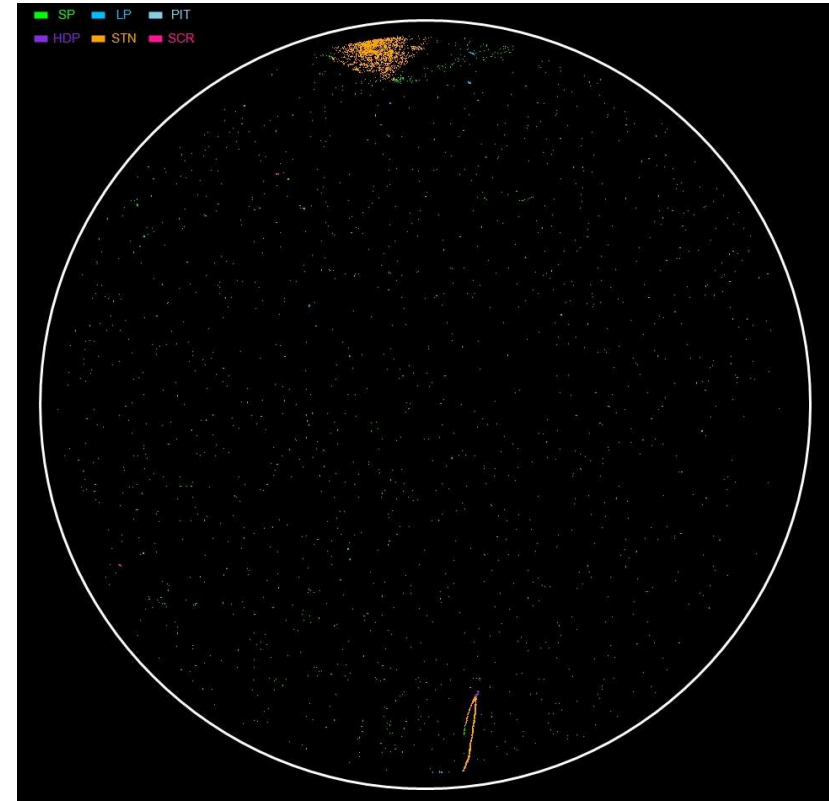
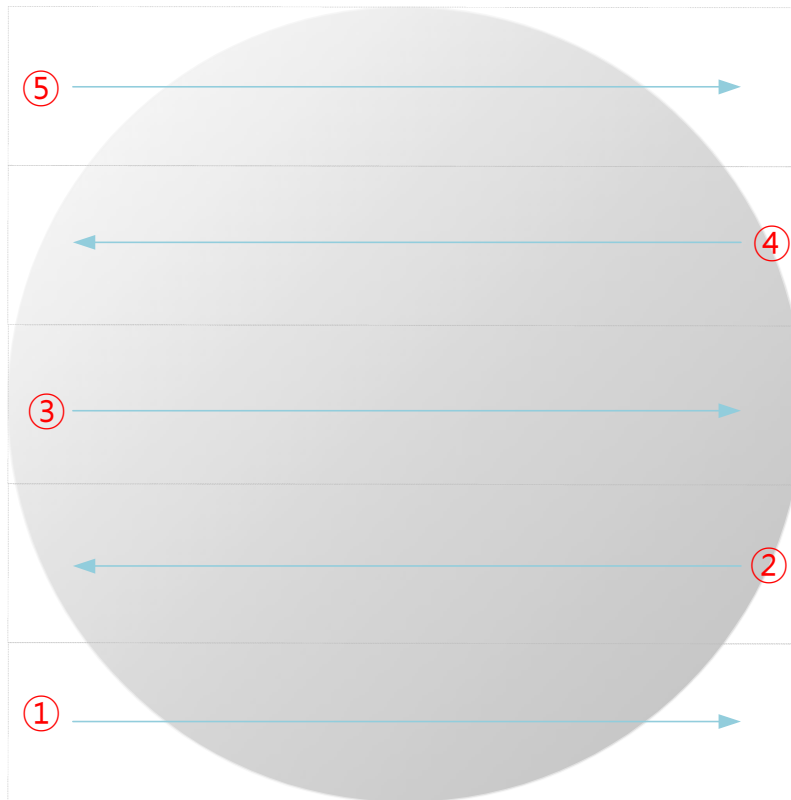
Use single high-performance line scan camera to improve **image quality** and **high uniformity**.

High performance processing and convenient to setup and maintenance.

5 steps for 300mm silicon wafer, 3 steps for 200mm silicon wafer.

COMIZOA 300mm

Front side Inspection



Use separated two high-performance line scan cameras. (Dark field and Bright Field)

High performance processing through simultaneous D.F and B.F scanning.

5 steps for 300mm silicon wafer, 3 steps for 200mm silicon wafer.

COMIZOA

Edge Surface Inspection System

Full automated camera and illumination system using modularized camera units and unified illumination unit for each function.

Use the optimized number(4) of **High-end industrial computers** compared to A company(8).

High speed and High accuracy control are acquired by using customized COMIZOA control system.

High Performance (Throughput) and Advanced Algorithms.

Folding Finger Spider system - Dynamic folding edge grip finger for single turn wafer inspection.

Optimized Equipment Software developed by the manufacturer itself.

Free Calibration wafer in buffer stage.

High reliability and stability.

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Thank you.

